

Ion-sensitive field-effect transistors

Basics and Applications

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- THEORY
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Introduction

- Introduction of potentiometric sensors
 - Measuring the electrical potential difference at a solid/liquid interface
 - Nernst Equation
 - $\Delta\phi = \frac{RT}{F} \ln \frac{a_{i1}}{a_{i2}}$
 - $a_{i1,2} = f_i c_i = \text{activity of ions } i$
 - Constant potential drop at the inner surface of the bulb
 - Contact between inner KCl solution and the outer solution
 - Electrochemical couple

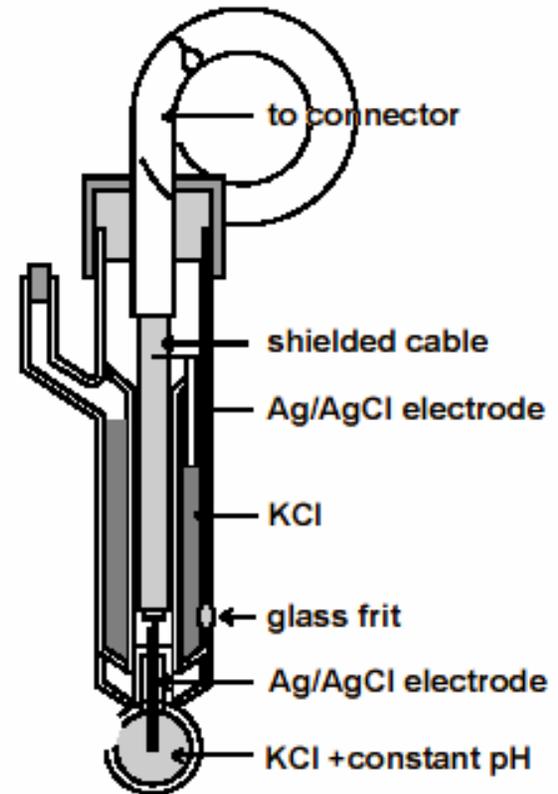
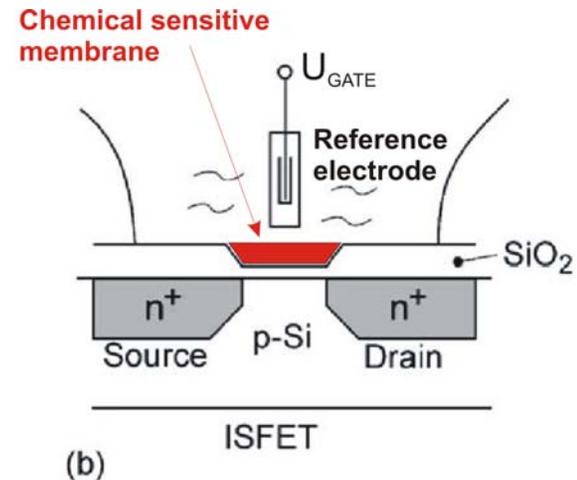
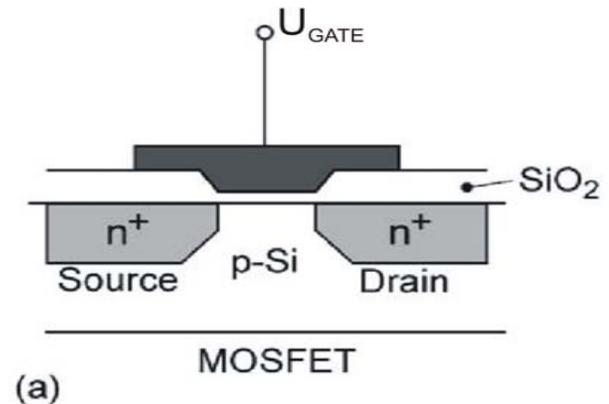


Fig.1
Cross sectional view of combined pH electrode.

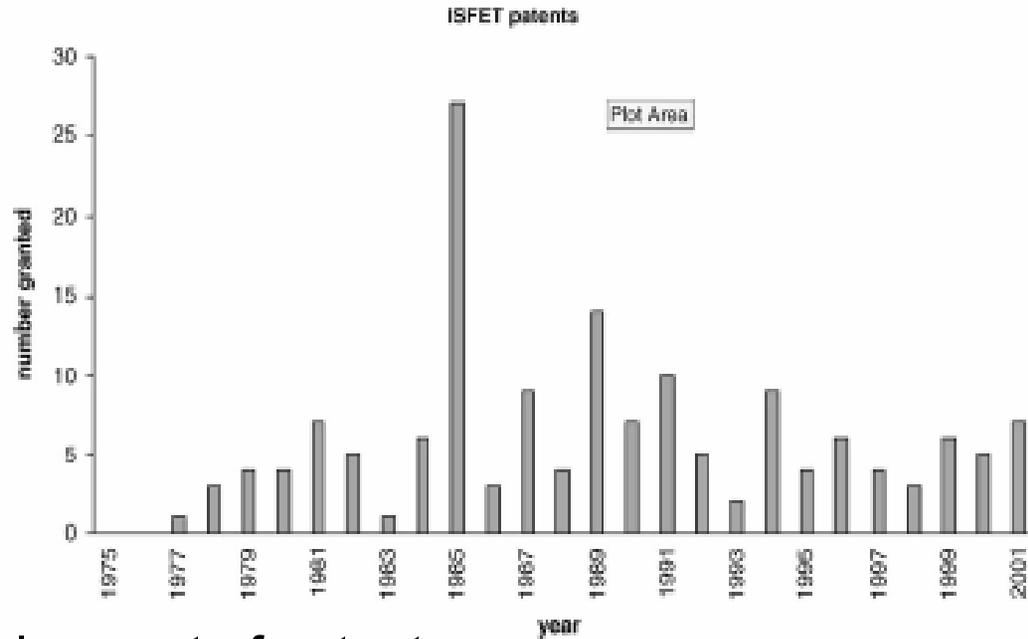
Introduction

- Problem of miniaturizing
 - Less stable
 - problematic for in vivo measurements
- Bergveld 1970: „Development of an Ion-Sensitive Solid-State Device for Neurophysiological Measurements“
- Advantage of chip technology
 - cheaper
 - Improved characteristics
 - Reproducibility
- Ion-Sensitive Field-Effect Transistor (ISFET)
 - small and rigid
 - fast response



Introduction

F. Bergveld/ Sensors and Actuators B 88 (2003) 1–20



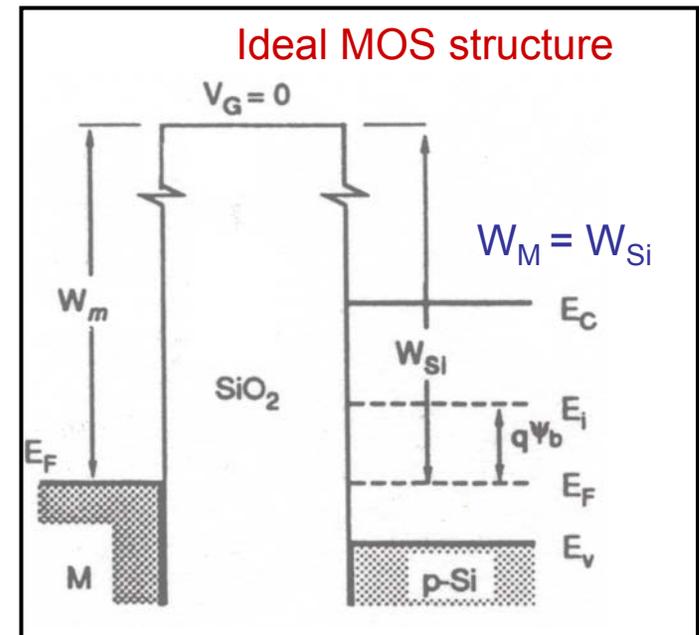
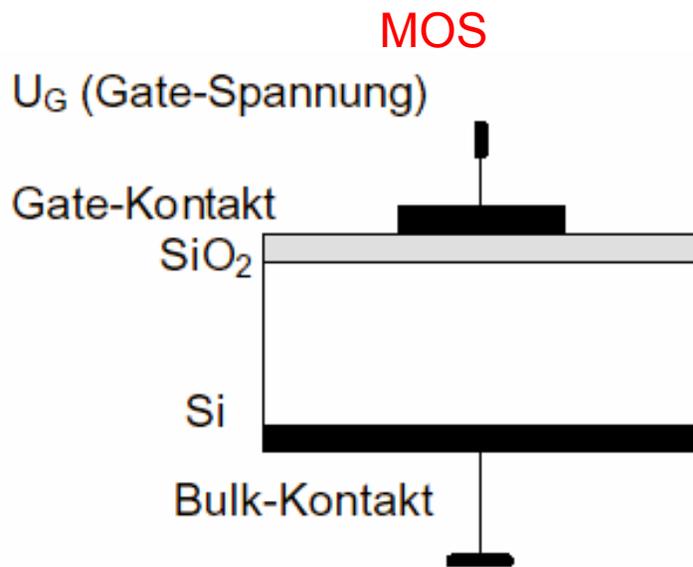
- Industry: Development of patents
- Markets:
 - Food industry
 - Biomedical industry
- Biocompatibility is still a big problem for in vivo measurements
- Future: inline-monitoring of industrial processes

MOSFETs

MOS-system

- Metal – Oxide – Semiconductor
 - Field effect: Voltage V_G induces charges at the surfaces \rightarrow electric field
 - Ideal MOS-structure
 - $W_M = W_{Si}$
 - perfect insulator
 - no charges inside the oxide

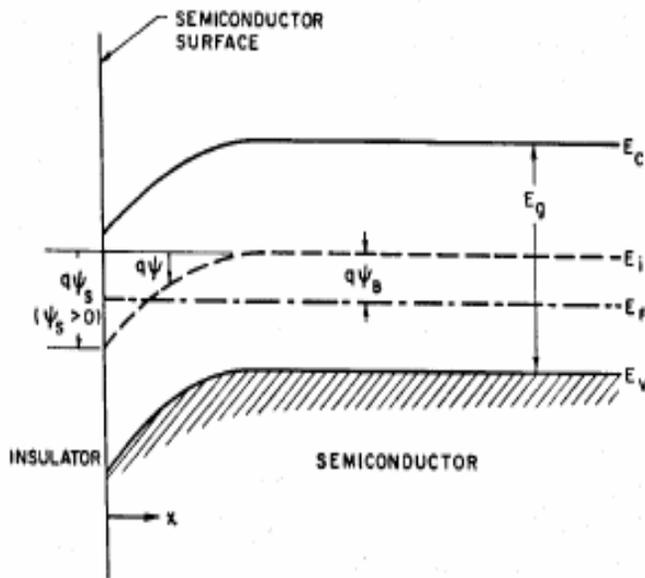
ψ_B = difference between intrinsic fermi energie E_i and fermi energie E_F after doping



MOSFETs

MOS-system

- Apply a voltage V_G
 - Inducing surface charges /space charges
 - Bending: due to surface charges/applied potential



Ψ_S = potential at the semiconductor surface,
determines the bending

Calculation by solving Poisson Equation

Boundary conditions:

- electric field $E = 0$ inside sc
- electric field $E \sim Q_S$

Leads to a relation between surface charges
 Q_S and the surface Potential

$\Psi_S = 0 =$ Flatband condition (ideal MOS)

MOSFETs

MOS-system

P-type
semiconductor

$$V_G < 0$$

$E_{F,M}$ increasement

→ upward bending

Accumulation fo holes at the sc/
oxide inetrface

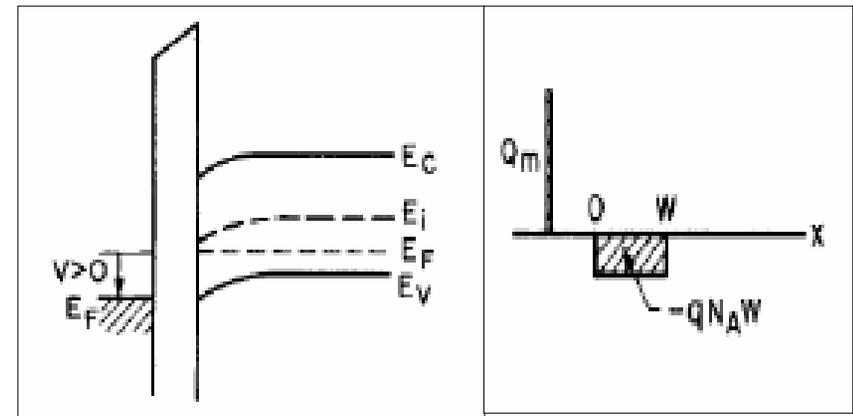
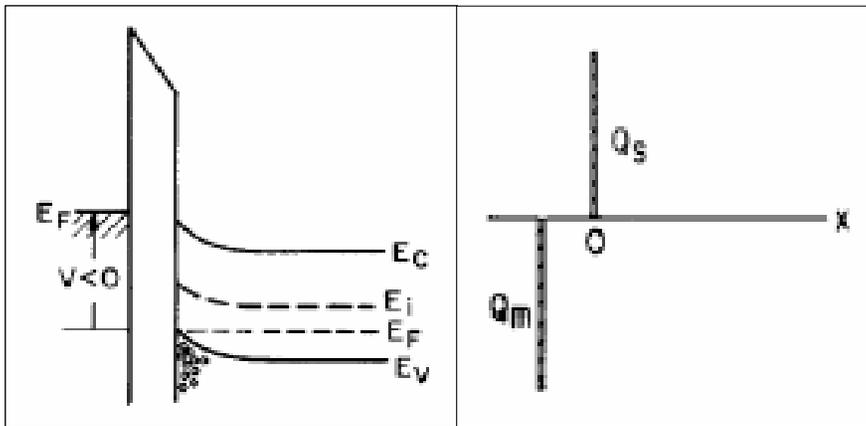
$$V_G > 0$$

$E_{F,M}$ decreasement

→ downward bending

Depletion of charge carriers (holes)
negative space charge

(insulating layer)



MOSFETs

MOS-system

P-type
semiconductor

$V_G \gg 0$: Inversion

Strong downward bending \rightarrow

$E_i < E_F$: E_F closer to E_C than to E_V

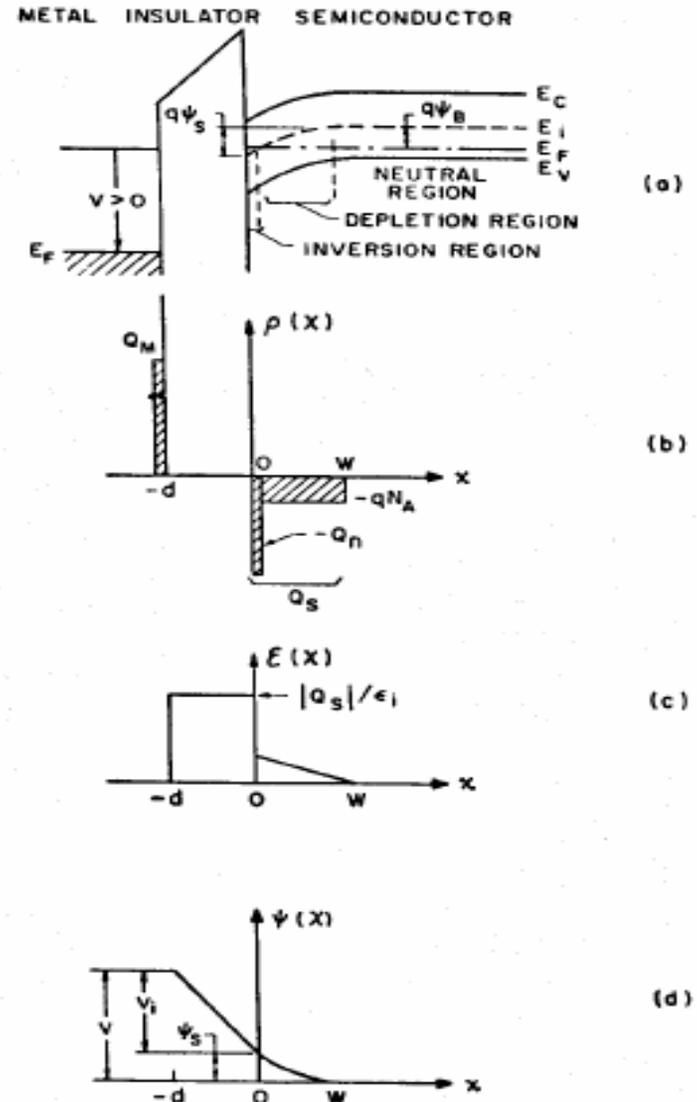
$N_e > N_h$

Strong depletion:

SC far away from Equilibrium $n \cdot p = n_i^2$

\rightarrow generation of electron-hole couples

accumulation of electrons at the Si/Ox interface



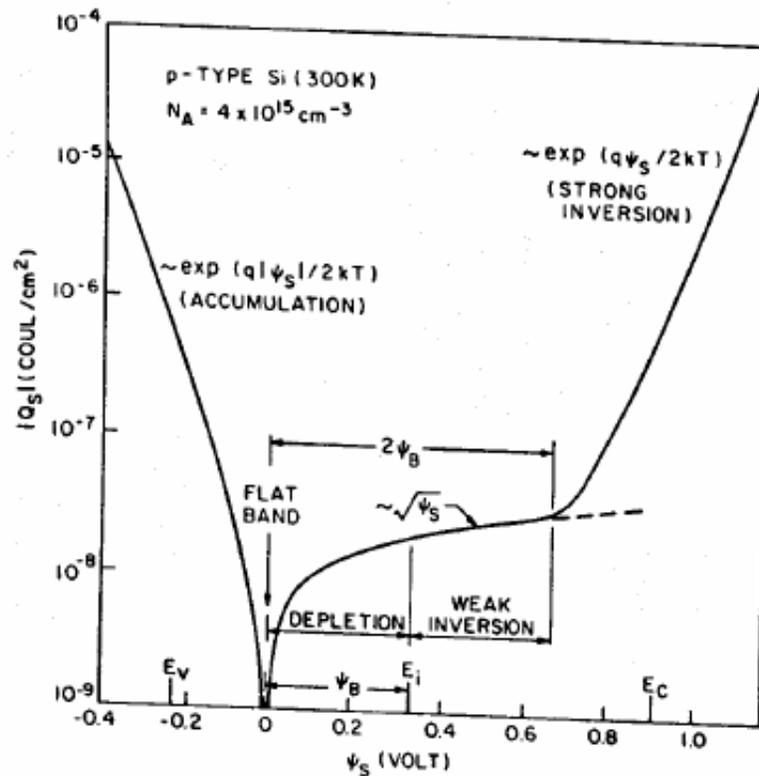
MOSFETs

MOS-system

Distribution of surface charge Q_s

n – type semiconductor

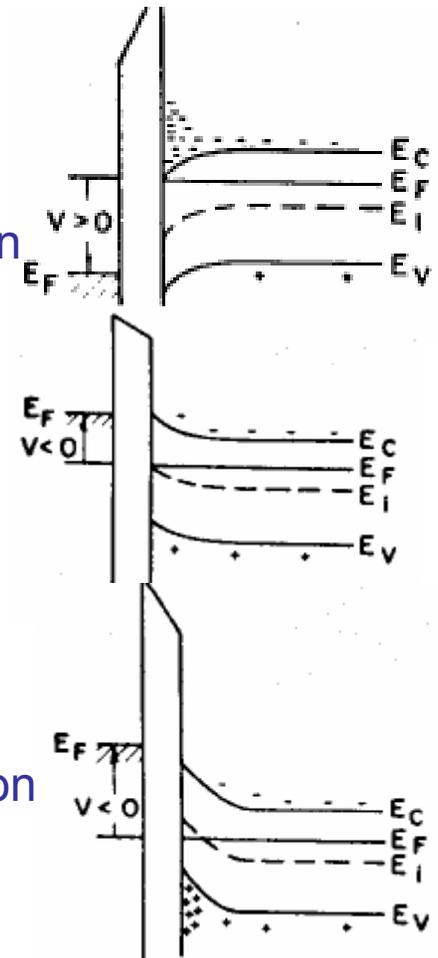
Equivalent situation, with changed polarity



accumulation

depletion

inversion



MOSFETs

MOS-system

Strong inversion
definition:

$$\Psi_S(inv) = 2\Psi_b$$

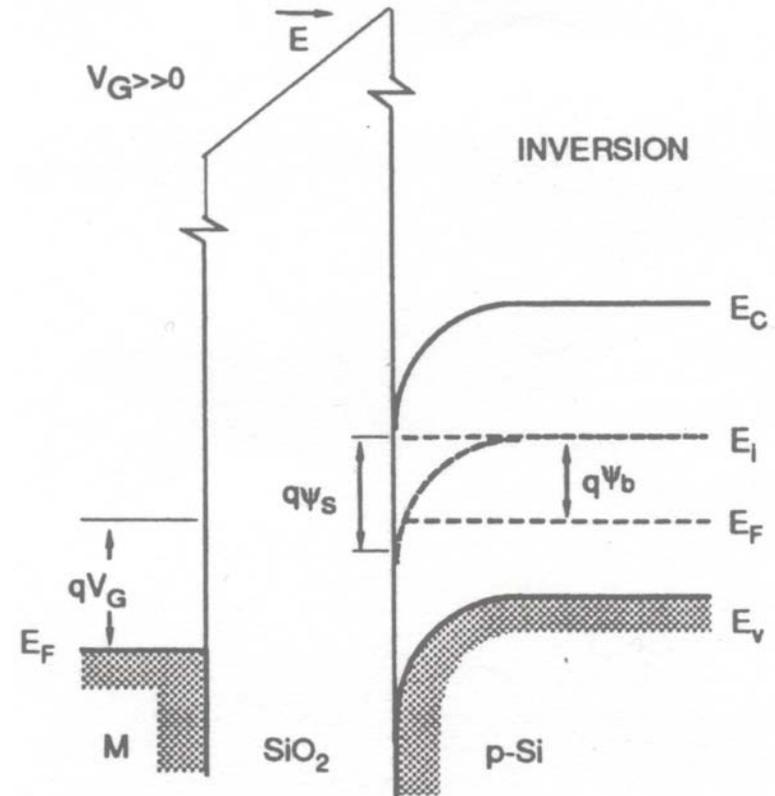
Threshold voltage U_T :

voltage required to induce and
inversion layer

$$U_T = U_G(inv) = 2\Psi_b + \Psi_i$$

$$\Psi_i \equiv \frac{-Q_D}{C_i} = \frac{-Q_D}{\epsilon_i} d_i \equiv \text{potential across the insulator}$$

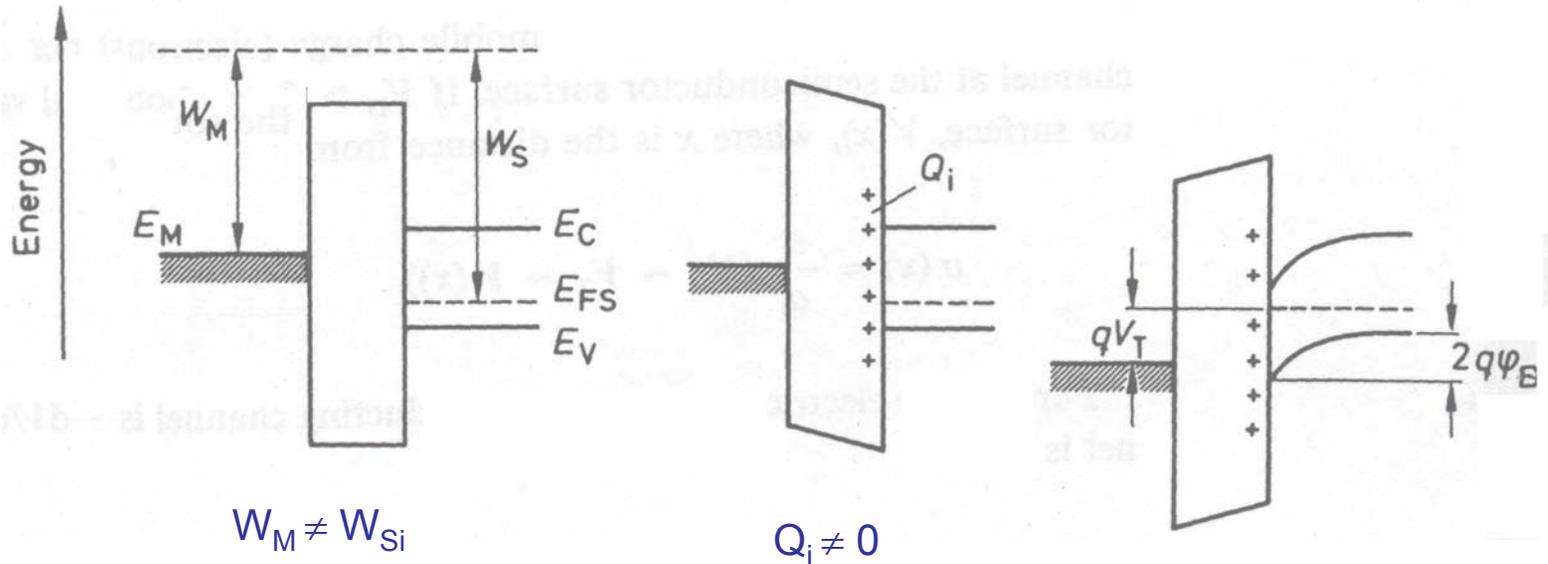
$$-Q_D \equiv -qN_A^-W_d \equiv \text{depletion region charge}$$



MOSFETs

MOS-system

Non-ideal MOS structure

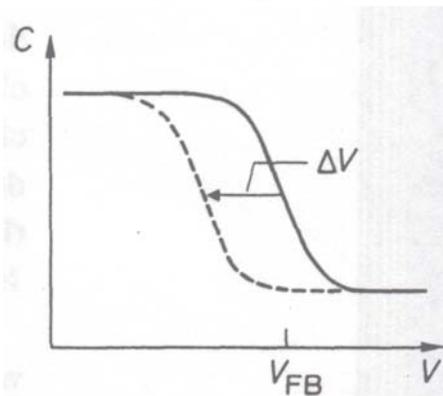
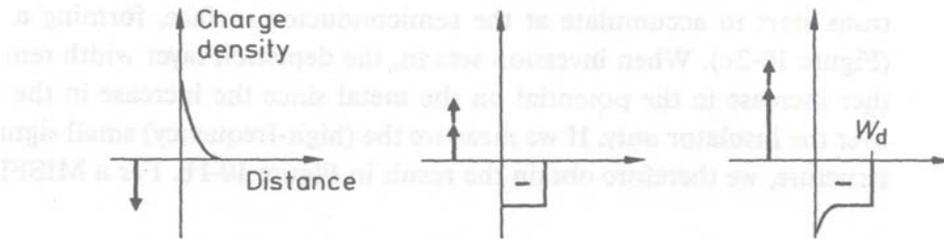
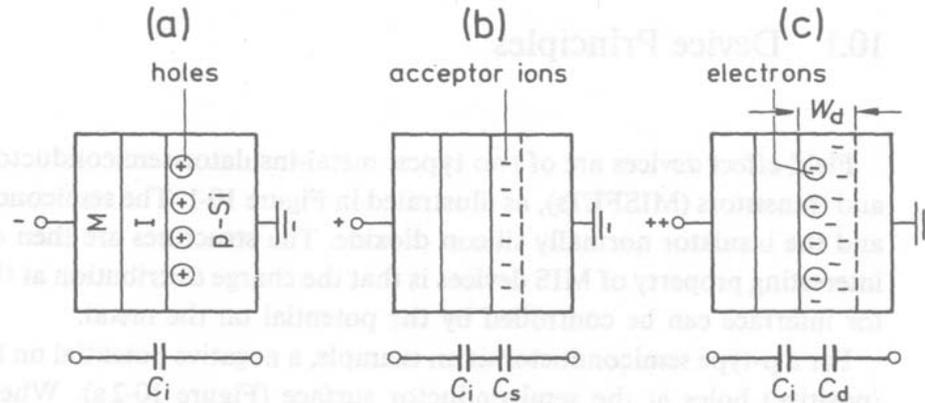


Flat-band voltage:
$$U_{FB} = \frac{\Delta W_{m/Si}}{q} - \frac{Q_i}{C_i} \quad \Rightarrow \quad U_T = U_{FB} - \frac{Q_D}{\epsilon_i} d_i + 2\psi_b$$

Voltage required to induce an inversion layer: first must achieve flat-band condition, then accommodate the charge in the depletion region and finally induce the inversion region

MOSFETs

MOS-system



a) accumulation:

$$C = C_{\max} = C_i$$

b) depletion:

$$1/C = 1/C_i + 1/C_s$$

$$C < C_{\max}$$

c) inversion:

low frequencies (< 100 Hz)

$$C = C_{\max}$$

high frequencies (> 100 Hz)

recombination/regeneration of electron – hole couples cannot keep up with voltage variation

→ depletion zone acts as a dielectric

$$C = C_{\min}$$

MOSFETs

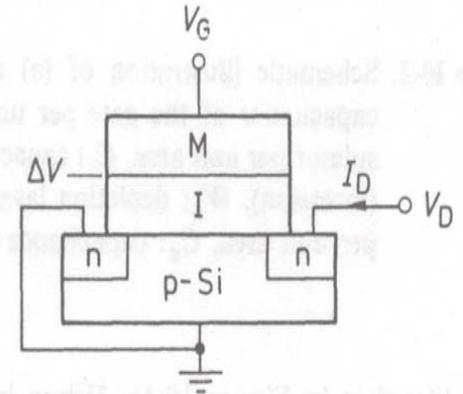
MOSFET operation

$V_G = 0$: two contra biased p-n junctions

$I_D =$ leakage current

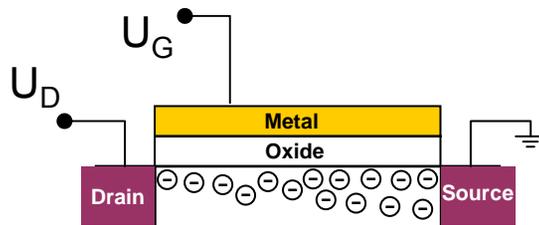
$V_G > V_T$: Inversion channel induced

I_D can flow

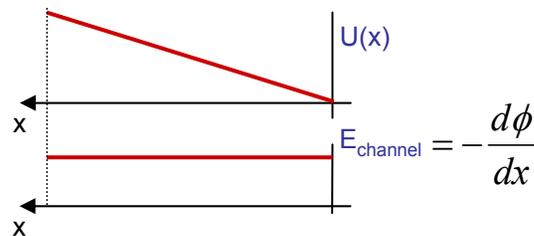


$$C = \frac{dQ}{dU} \Rightarrow \sigma = \frac{\epsilon_i}{d_i} (U_G - U_T) \equiv \text{induced mobile charge (C/m}^2\text{) in the conducting channel}$$

$U_{DS}=0V$



$$\sigma = \frac{\epsilon_i}{d_i} (U_G - U_T - U(x))$$



Linear decrease of $U(x)$ along the n-channel

$$U(0) = U_D$$

$$U(L) = 0$$

MOSFETs

MOSFET operation

Integration:

$$I_D = K \left((U_G - U_T) U_D - \frac{U_D^2}{2} \right)$$

for $U_D < U_G - U_T$ linear region

$U_D = U_G - U_T =$ pinch off

inversion channel vanishes

→ depletion remaining

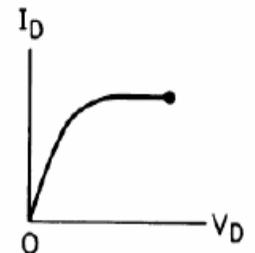
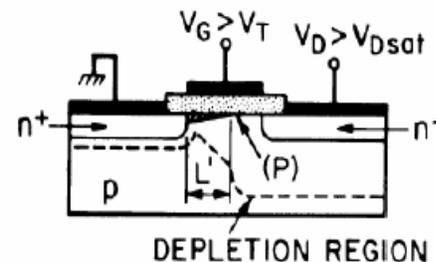
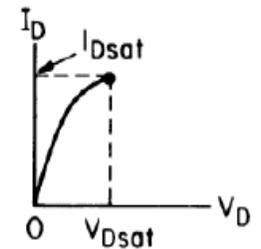
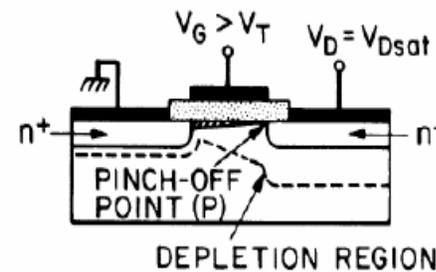
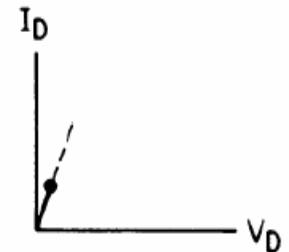
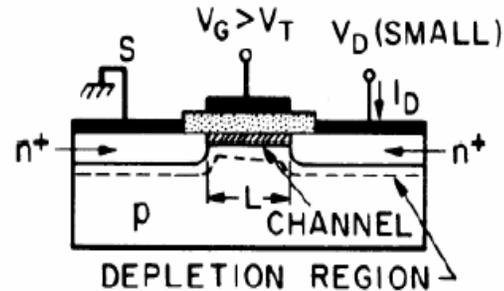
$U_D > U_G - U_T =$ saturation

Length of channel reduces

→ Resistance increases

→ I_D stays constant

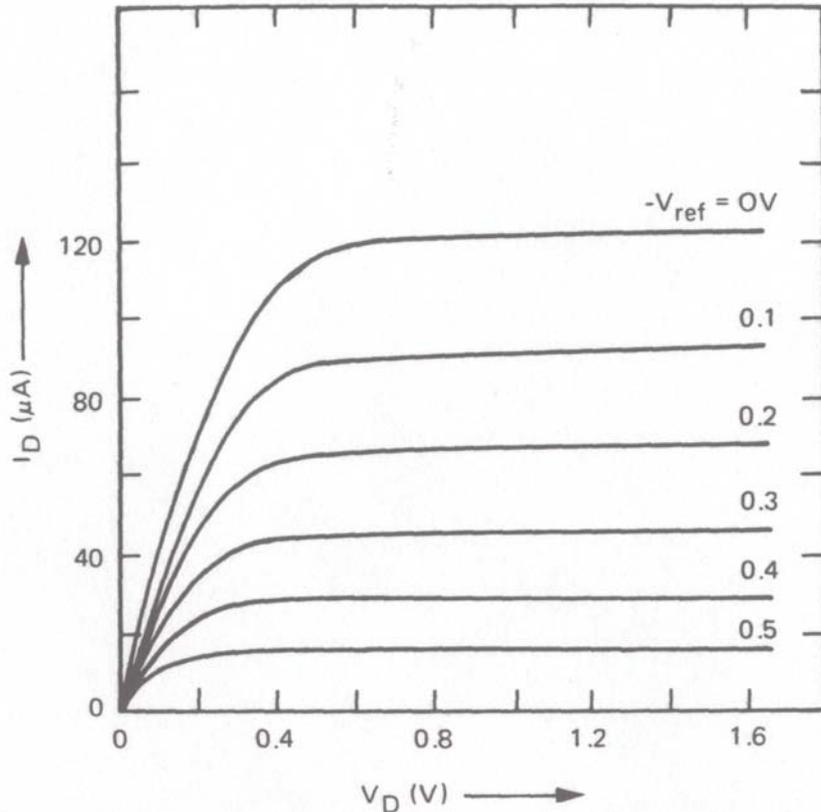
$$I_D = K \frac{(U_G - U_T)^2}{2}$$



MOSFETs

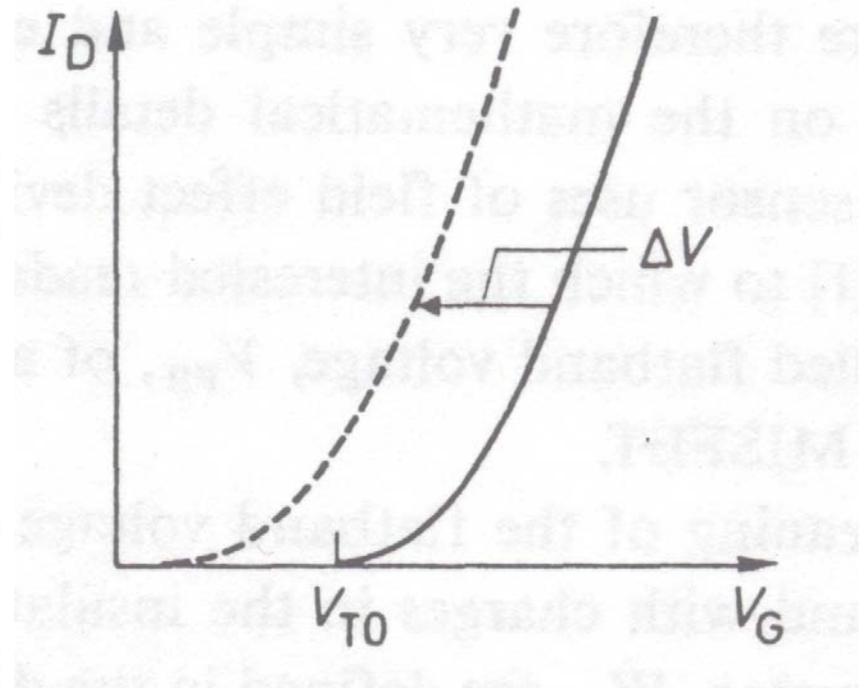
MOSFET operation

I_D vs. V_D at constant V_G



Voltage shifts:

required Flatband Voltage
in nonideal MOSFETs



U_T depends of oxide thickness: small $d_i \rightarrow$ big $C_i \rightarrow$ small U_T

limit: electric field strength for break through

ISFETs

Basic Idea: removal of the metal plate of an MOSFET and expose the oxide to an electrolyte

Important: encapsulation of the chip

U_G : Potential applied between reference electrode and earth

Possible Respond mechanisms:

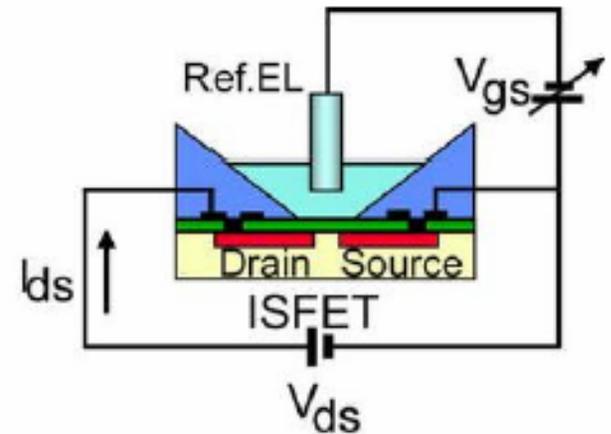
1. Interfacial potential at electrolyte-oxide interface (s.MOSFET)
2. Diffusion of species through the oxide

Diffusion: slow process ($d_{\text{oxide}} \sim 1000 \text{ \AA}$, $t \sim 10^4 \text{ s}$)

no dependence of oxide thickness has been watched

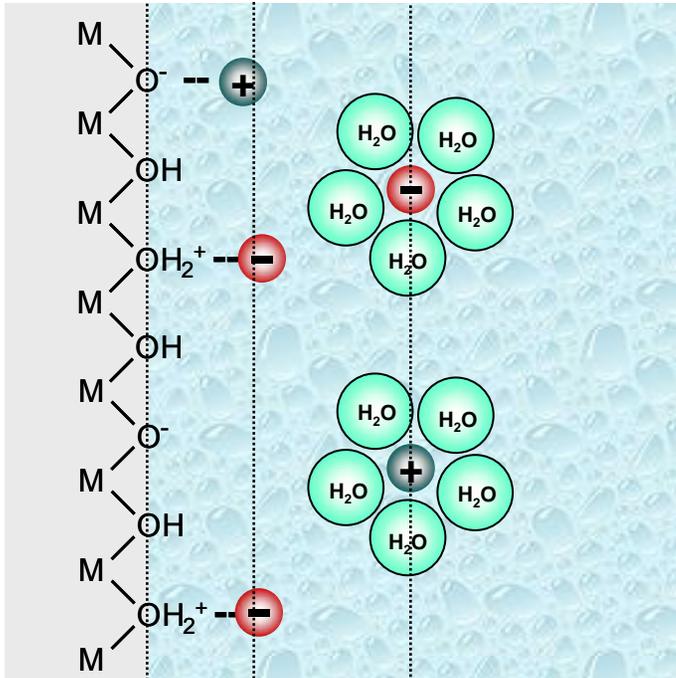
→ not the major respond mechanism

(current drift)



ISFETS

EOS-system



Electrolyte/Oxide/Semiconductor Interface

Inner Helmholtz Plane (IHP)

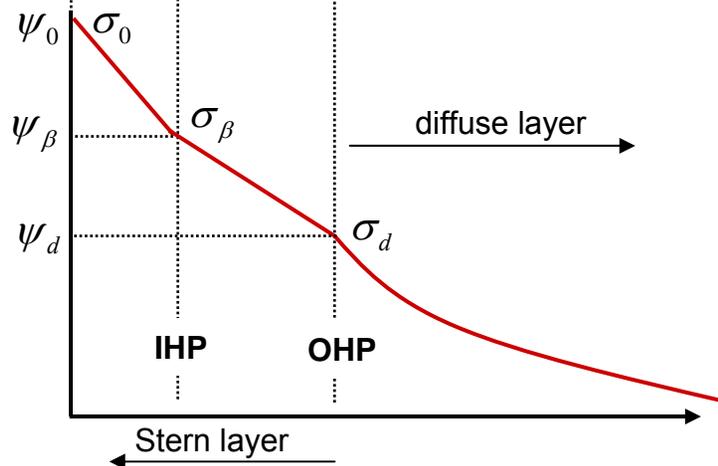
- Specifically adsorbed ions
- amphoteric hydroxyl groups

Outer Helmholtz Plane (OHP)

- closest approach of solvated ions

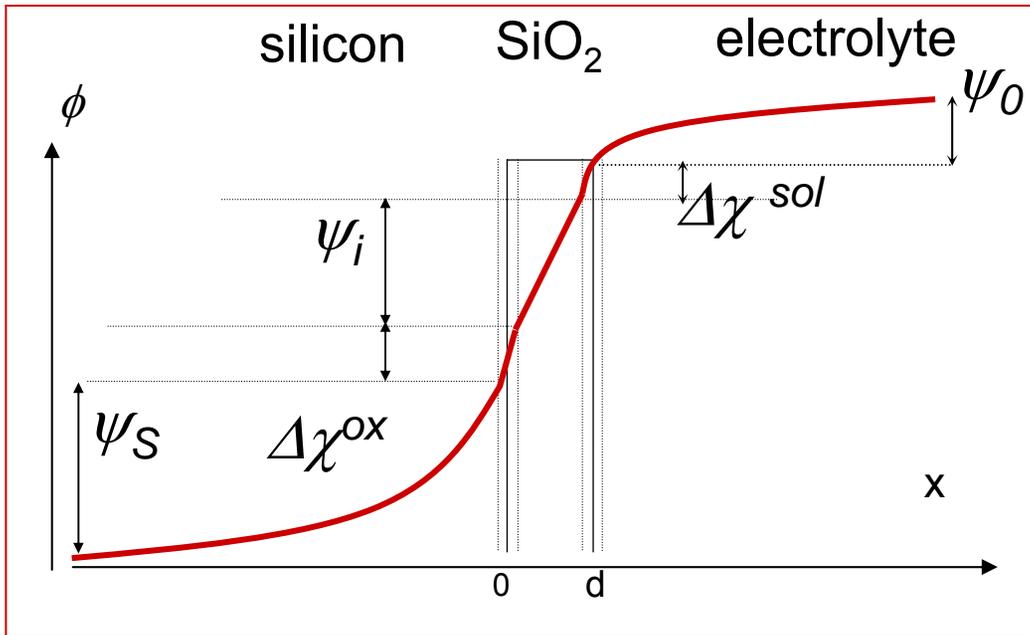
Diffuse (Gouy-Chapman) Layer

- diffuse charge region into the bulk electrolyte



ISFETS

EOS-system



flat band potential ($\psi_S=0$)



$$U_{FB} = U_{Ref} - \psi_0 + \chi^{sol} - \frac{W_{Si}}{q} - \frac{Q_i}{C_i}$$

$U_{Ref} \equiv$ reference electrode potential

$\psi_0 \equiv$ potential drop in the electrolyte

Potential drop across:

- Solution (Bulk \rightarrow diffuse layer \rightarrow OHP \rightarrow IHP)
- Oxide /Electrolyte surface dipoles
- Capacitance of the oxide
- Oxide/Semiconductor interface dipoles
- Semiconductor

$W \equiv$ Si work function

$Q_i / C_i \equiv$ oxide potential drop

$\chi^{sol} \equiv$ electrolyte surface dipole potential

ISFETS

EOS-system

First Approach: Nernst Equation

Interface between solid (oxide) and liquid (electrolyte)

Equilibrium: $\mu_i^{\text{ox}} = \mu_i^{\text{sol}}$

Electrochemical Potential in one phase

$$\mu_i = \mu_i^0 + RT \ln a_i + z_i F \Phi$$

a_i = activity of component i

$$a_{\text{ox}} = 1$$

Potential difference: Galvani Potential

$$\Delta \Phi = \Phi_{\text{sol}} - \Phi_{\text{ox}} = \Delta \mu_i^0 + RT/F \ln (a_i^{\text{sol}})$$

$$\text{For } i = \text{H}^+: U_{\text{interface}} = E_0 + RT/F \ln(a_{\text{H}^+})$$

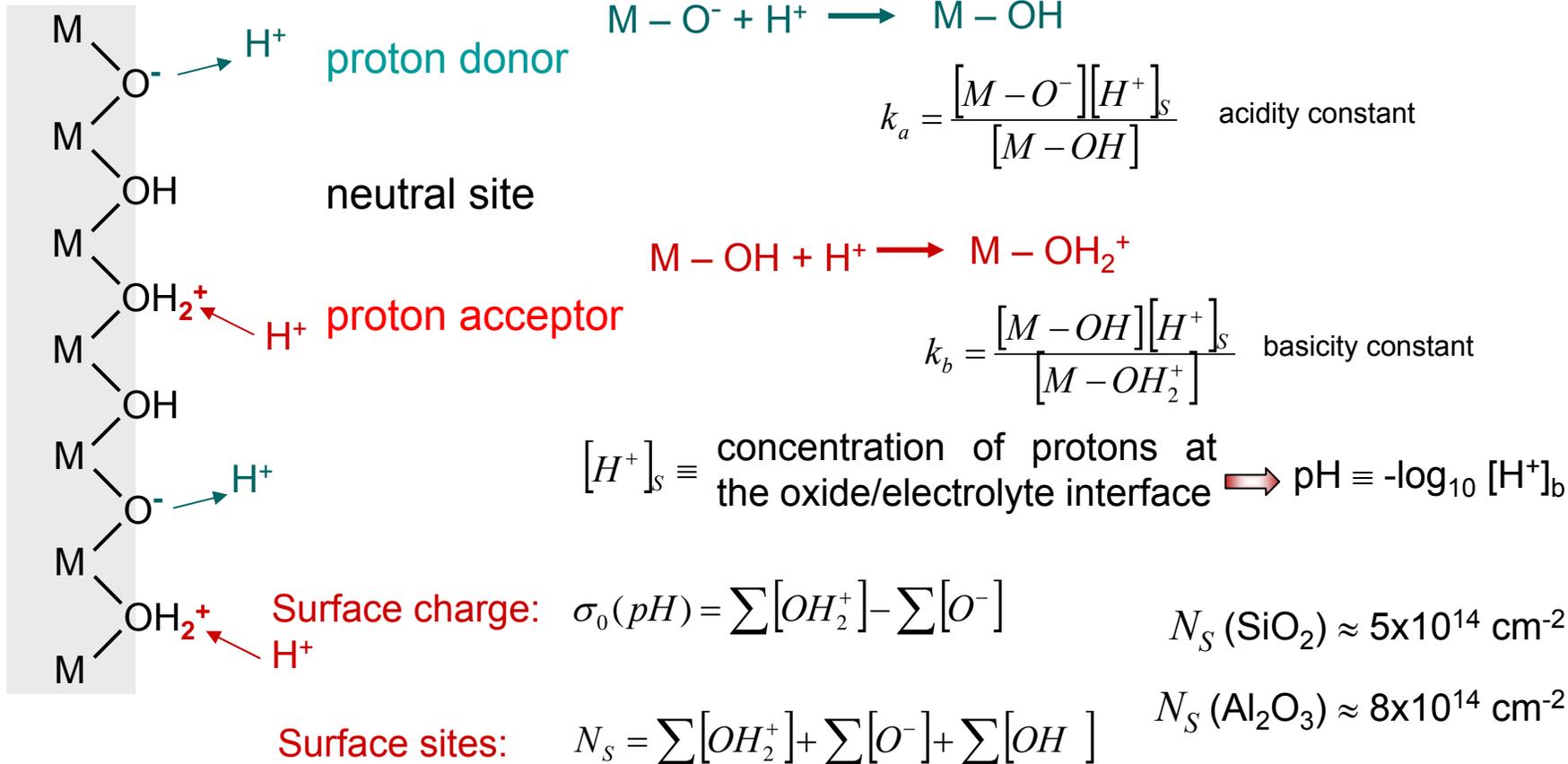
In real measurements: strong deviations from Nernstian behaviour

For good insulators (Si_3N_4 , Al_2O_3) thermodynamic equilibrium between electrolyte and oxide cannot be achieved

ISFETS

pH-sensitivity and Site-Binding Model

Amphoteric behaviour of Oxides



ISFETS

pH-sensitivity and Site-Binding Model

Equilibrium of H^+ between the oxide surface and the bulk solution

Ψ_0 = potential difference between surface and bulk solution = $\Psi_s - \Psi_b$

$[H^+]_s$ related to $[H^+]_b$ by equating the electrochemical potential

$$\Rightarrow \mu_{H^+}^s + kT \ln[H^+]_s + q\psi_0 = \mu_{H^+}^b + kT \ln[H^+]_b$$

$$[H^+]_s = [H^+]_b \exp\left(\frac{-q\psi_0}{kT}\right) \exp\left(\frac{\mu_{H^+}^b - \mu_{H^+}^s}{kT}\right)$$

constant

$$\Rightarrow [H^+]_s = [H^+]_b \exp\left(\frac{-q\psi_0}{kT}\right)$$

Boltzmann...

ISFETS

pH-sensitivity and Site-Binding Model

Number of Surface sites: $N_s = \sum[OH_2^+] + \sum[O^-] + \sum[OH]$

Results in a surface charge $\sigma_0(pH) = \sum[OH_2^+] - \sum[O^-]$

$$\sigma_0 = 0$$



$pH_{pzc} = pH$, at which the total surface charge is zero

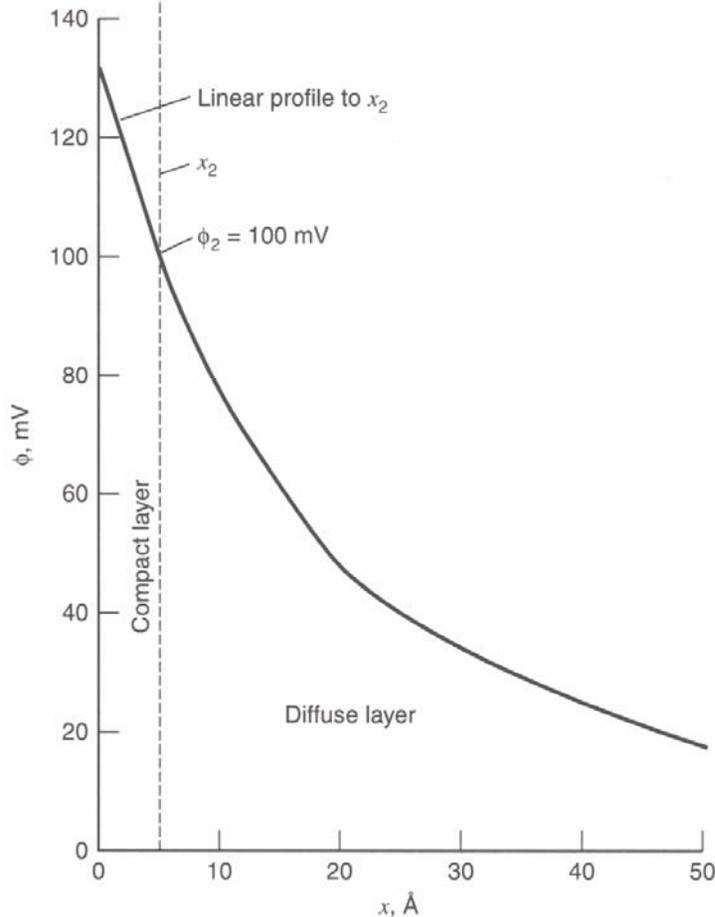
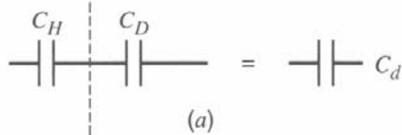


With previous equations , this is leading to:

$$2.303 \cdot (pH_{pzc} - pH) = \frac{e\psi_0}{kT} + \ln \left(\frac{[M - OH_2^+]}{[M - O^-]} \right)^{\frac{1}{2}}$$

ISFETS

pH-sensitivity and Site-Binding Model



$$-\psi_0 = \frac{\sigma_d}{C_H} + \frac{2kT}{q} \sinh^{-1} \left(\frac{\sigma_d}{(8kT\epsilon\epsilon_0 n^0)^{1/2}} \right)$$

potential drop in the Helmholtz double layer

potential drop in the diffuse layer

when the ion concentration in the solution (n^0) is medium-high

$$\psi_0 = \frac{-\sigma_d}{C_d} = -\sigma_d \left(\frac{1}{C_H} + \frac{2kT}{q} (8kT\epsilon\epsilon_0 n^0)^{1/2} \right)$$

ISFETS

pH-sensitivity and Site-Binding Model

using the *charge neutrality* equation



$$\sigma_0 + \sigma_d = -(Q_{Si} + Q_i)$$

$Q_{Si} \equiv$ charge in the Si inversion channel

$\sim 10^{11}$ charges/cm²

$$\hookrightarrow Q_{Si} \approx 10^{-8} \text{ C/cm}^2$$

$Q_i \equiv$ charge inside the insulator

$$Q_i \ll Q_{Si}$$

$\sigma_0 \equiv$ charge on the insulator surface

$\sigma_d \equiv$ charge on the electrolyte side of the double layer

\hookrightarrow dominated by C_H ($\sim 10^{-5}$ F/cm²)

$$\hookrightarrow \sigma_d \approx 10^{-5} \text{ C/cm}^2$$

$$\sigma_d \gg Q_{Si}$$

$$\Rightarrow \sigma_0 = -\sigma_d$$

$$\sigma_0 = \psi_0 C_d$$

linear relation between surface charge and potential

ISFETS

pH-sensitivity and Site-Binding Model

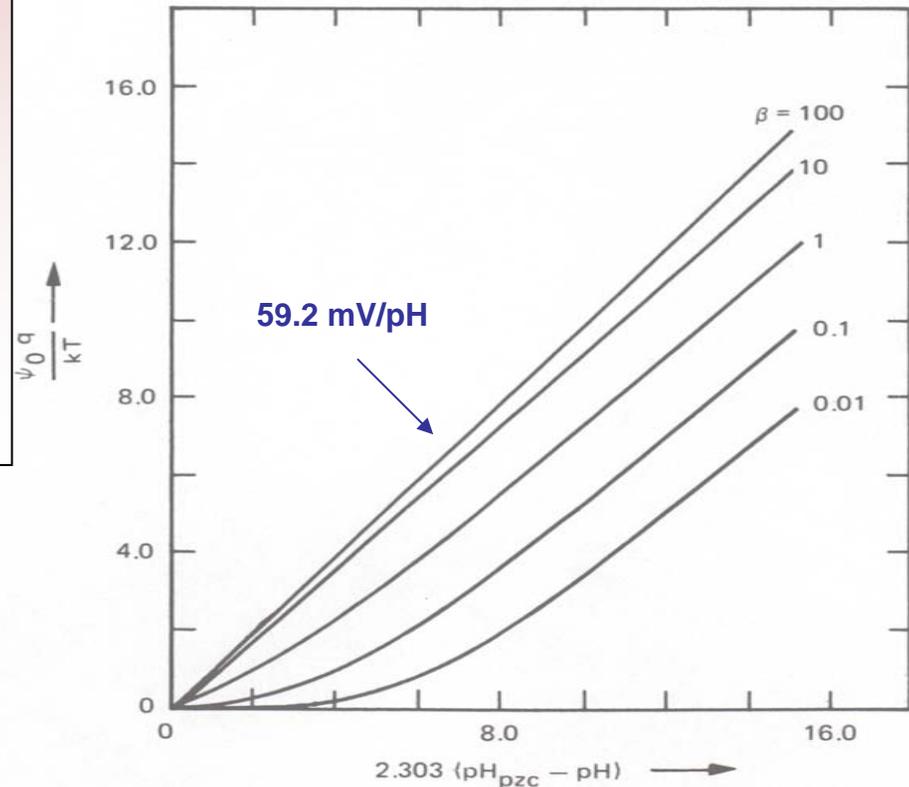
Leading to an expression for the pH sensitivity of an ISFET

$$\psi_0 = 2.303 \frac{kT}{q} (pH_{pzc} - pH) \left(\frac{\beta}{1 + \beta} \right)$$

$$\beta = \frac{2q^2 N_s (k_a k_b)^{1/2}}{kTC_d} \equiv$$

sensitivity factor

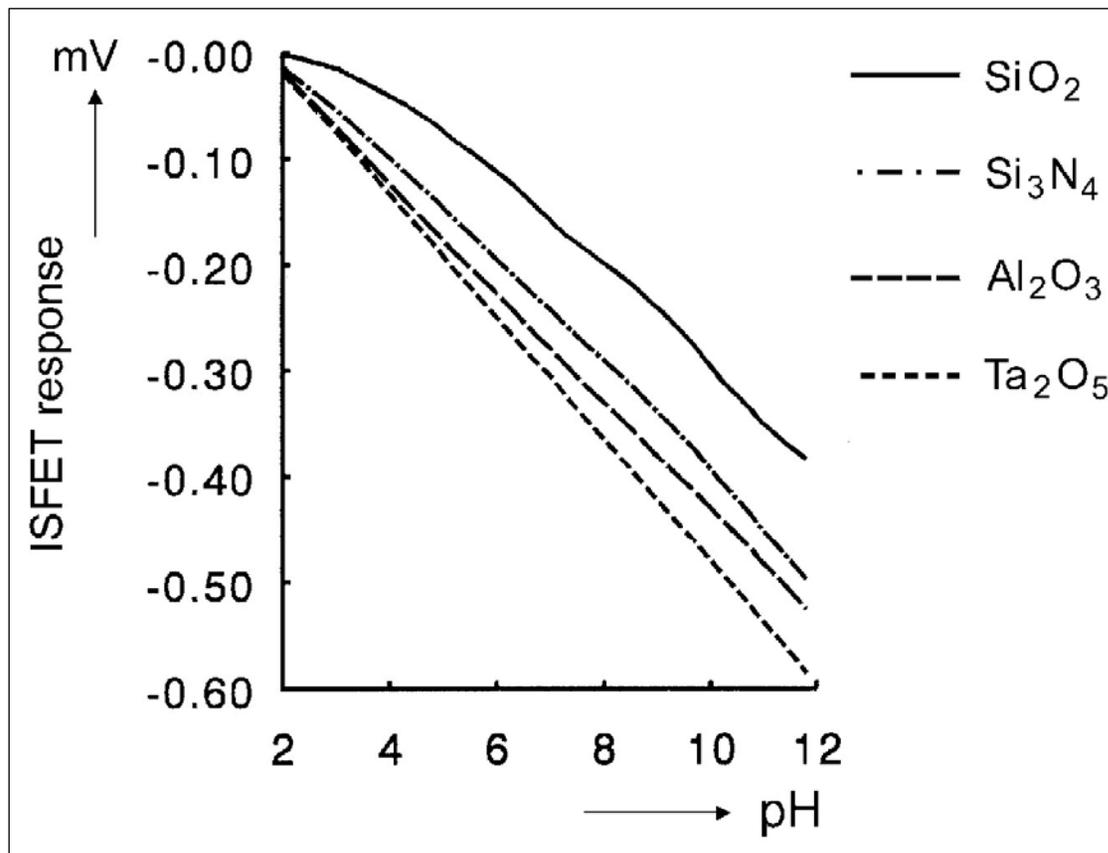
For $\beta \gg 1$: Nernstian Response



ISFETS

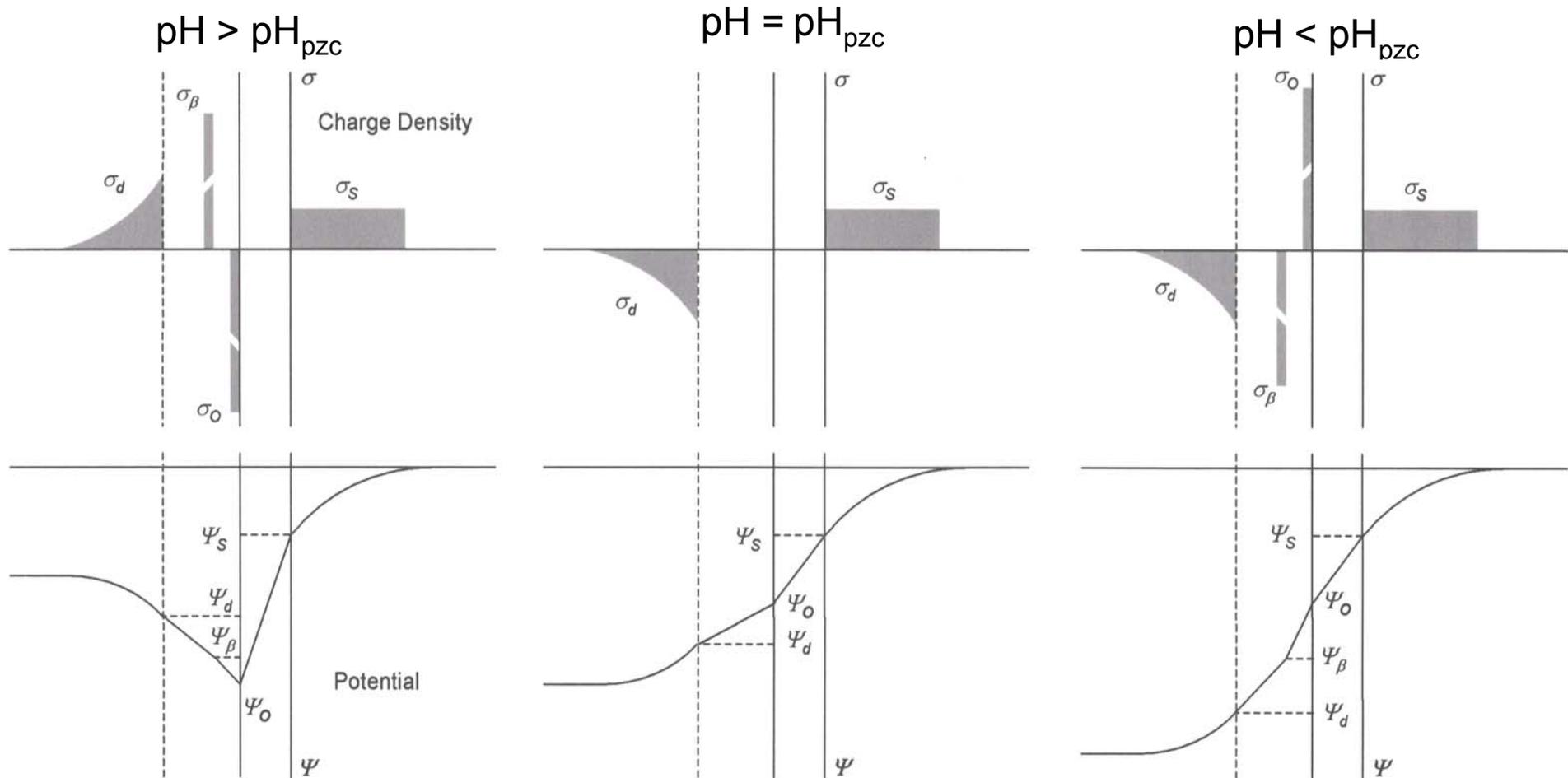
pH-sensitivity and Site-Binding Model

Sensitivity depends on the used oxide material



ISFETS

pH-sensitivity and Site-Binding Model



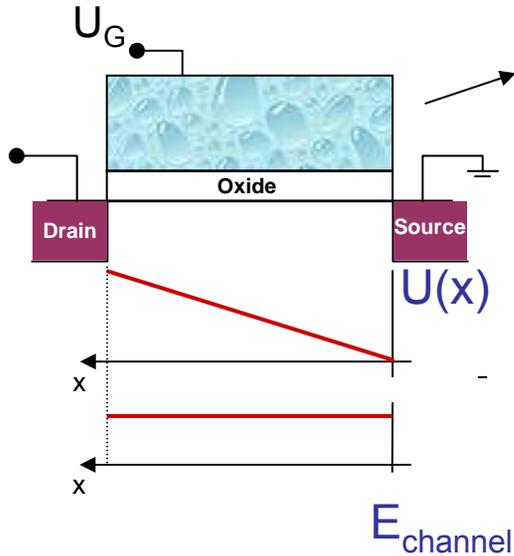
$$U_G = U_{Ref} + \frac{1}{q} W^{Si} - \psi_0 - \frac{Q_i}{C_i} + \psi_s + \chi^{sol}$$

$$\psi_0 = 2.303 \frac{kT}{q} (pH_{pzc} - pH) \left(\frac{\beta}{1 + \beta} \right)$$

ISFETS

pH-sensitivity and Site-Binding Model

Reminding the MOSFET/ ISFET concept



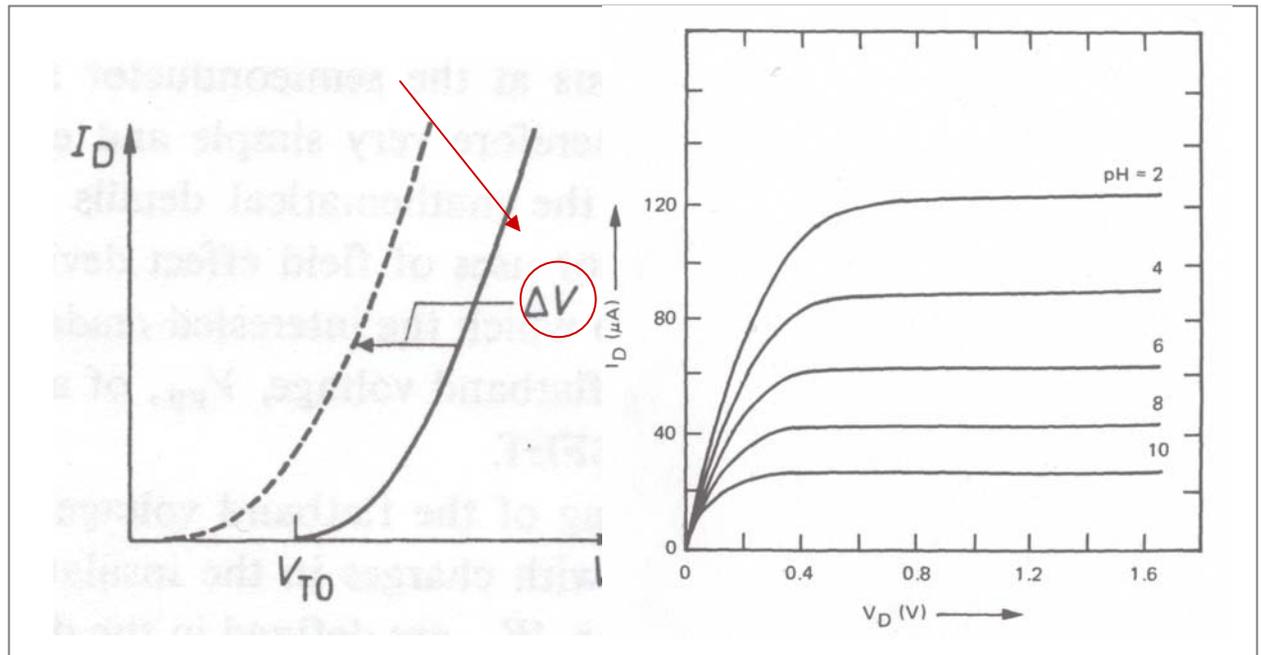
$$U_T = U_{FB} - \frac{Q_D}{\epsilon_i} d_i + 2\Psi_b$$

$$I_D = K \frac{(U_G - U_T)^2}{2}$$

$$U_{FB} = U_{Ref} - \psi_0 + \chi^{sol} - \frac{W_{Si}}{q} - \frac{Q_i}{C_i}$$

$$\psi_0 = 2.303 \frac{kT}{q} (pH_{pzc} - pH) \left(\frac{\beta}{1 + \beta} \right)$$

$$\psi_0(pH) \Rightarrow U_T(pH)$$



ENFETs

Concept

Functionalisation of oxide surfaces

Deposition of polymeric membranes on the gate insulator

→ Matrices for immobilisation of enzymes

Common material: polyvinylchloride (PVC)

Immobilisation mechanisms

- i) entrapment in polymeric network
- ii) entrapment in gel matrix
- iii) crosslinking with multi-functional agent
- iv) covalent bonding to sensor surface

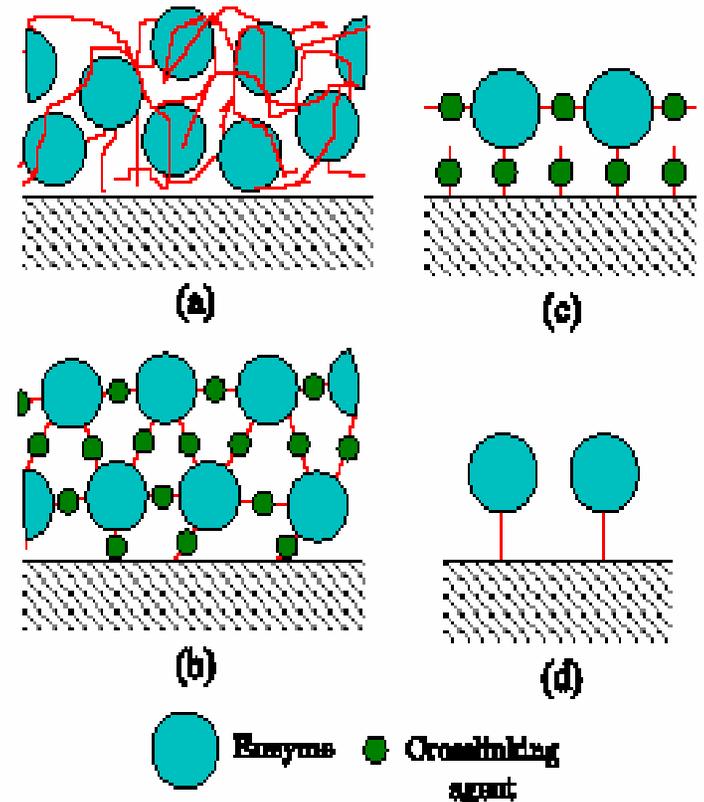
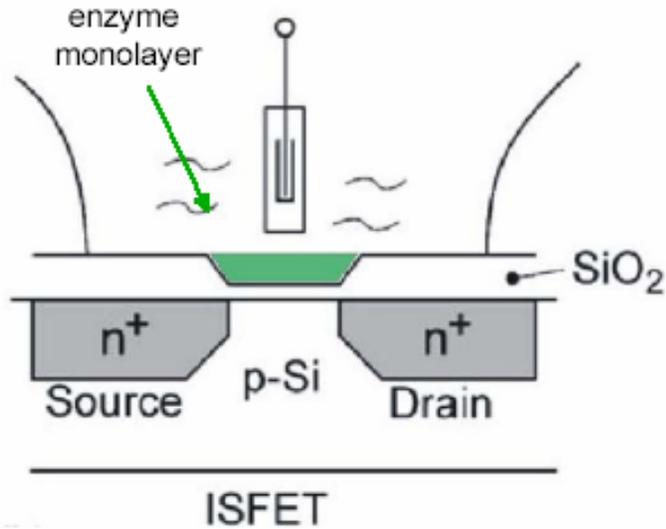


Fig. 4. Methods of enzyme immobilisation: a) entrapment in gel matrix, b) crosslinking with multi-functional agent, c), d) covalent bond with and without bi-functional agent respectively

ENFETs

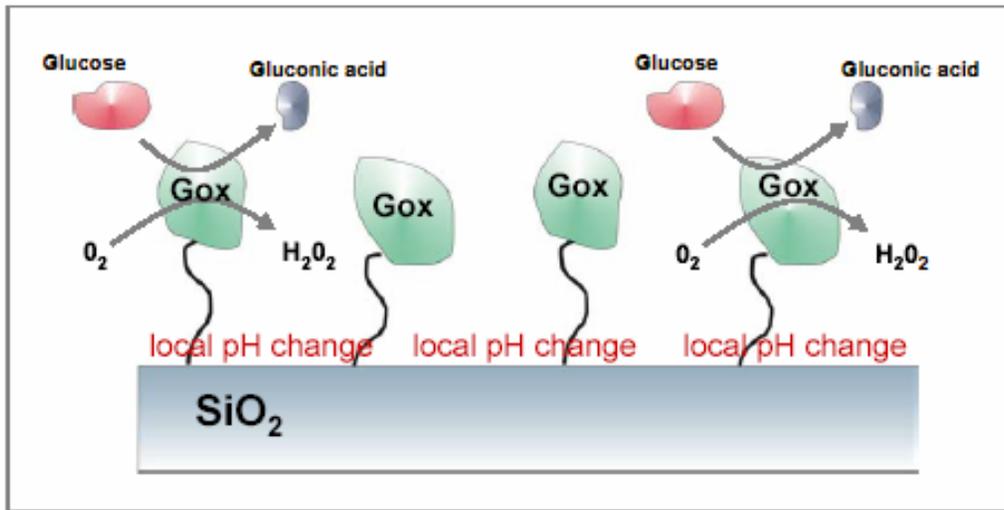
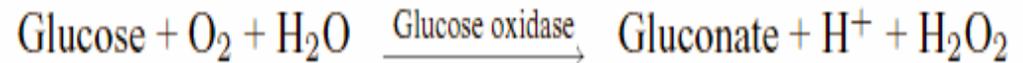
Glucose ENFET

Example



Glucose oxidase immobilised at the insulator surface

Reaction in membran layer



local pH change induced by enzyme biocatalyzed transformations

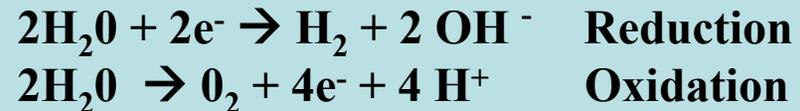
Detection of pH change with ISFET structure

→ Detection of glucose

Sensor/Actuator Systems

Control of the pH of a solution = coulometry

Coulometric generation of H^+ / OH^- by electrochemical reactions at generating electrodes



Coulometry is an absolute method of ion generation

Boundary conditions

- i) well known stoichiometry
- ii) no side reactions occur
- iii) Current efficiency $\sim 100\%$

Sensor signal can be adjusted, to induce a defined change of pH

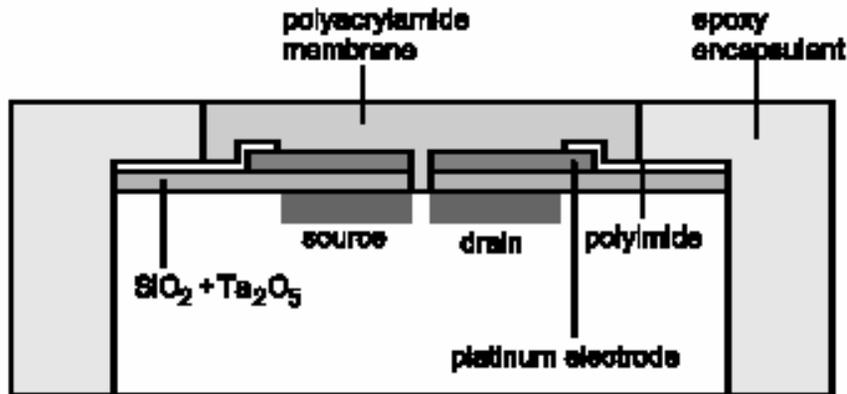
Sensor/Actuator Systems

Modified ENFET

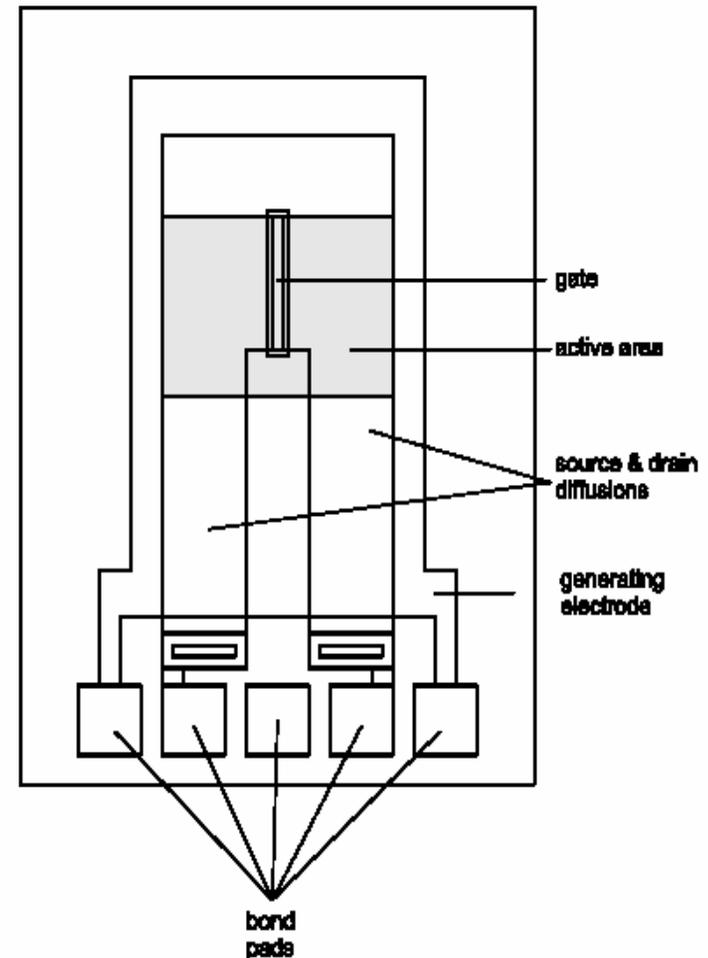
Generating platinum electrodes around gate

Excellent stability of urease →
ideal sensitive enzyme

Immobilised in polyacrylamide
membrane



(b)



Sensor/Actuator Systems

Limitation for simple ENFET

C_{buffer} , enzyme kinetics and reaction equilibrium depend on pH

ENFET: Strongly nonlinear response

Dynamic range depends on composition of the sample

Sensor/Actuator System:

ENFET measures pH inside membrane

→ pH control through coulometric generation of H^+/OH^-

Response of ENFET $\frac{\partial V_{\text{out}}}{\partial [S]} = EB / \beta$

B = sensitivity of ISFET

E = enzymatic sensitivity

β = buffer capacity

[S] = substrate concentration

$E > 0$ = acidic reaction

$E < 0$ = alkaline reaction

Sensor/Actuator Systems

Similar: electrochemical actuator

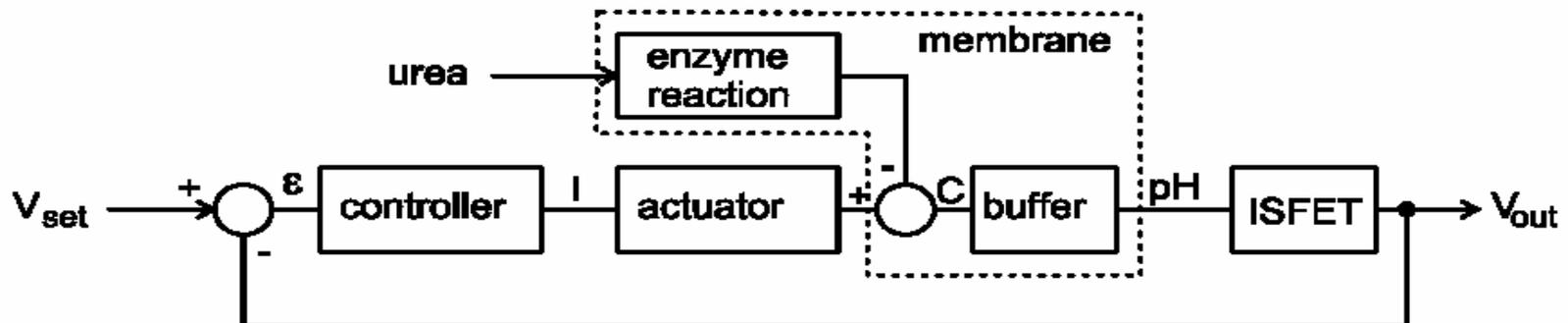
Small changes in pH: $\partial V_{out} / \partial I = AB / \beta$

I = current through generating electrode
A = sensitivity of sensor-actuator system

$$\partial V_{out,current} = -\partial V_{out,enzyme} \Rightarrow \partial I / \partial [S] = -E/A$$

⇒ Linear response on [S]

independent from buffer capacity



Sensor/Actuator Systems

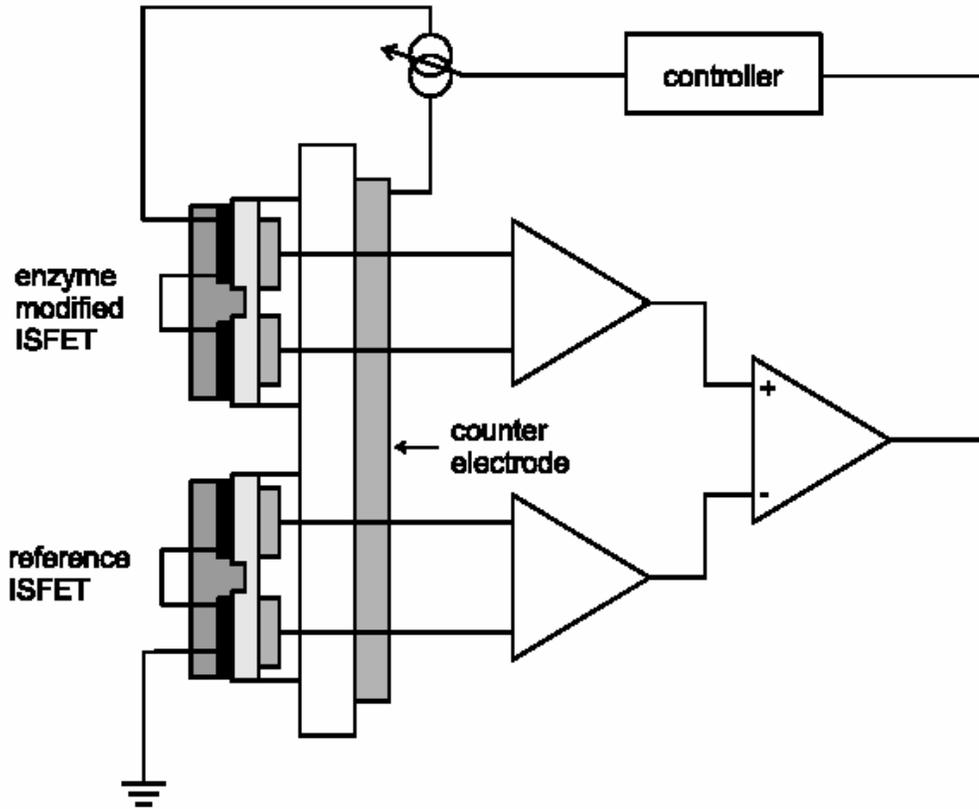


Fig. 12
Measurement set-up for the pH-static enzyme sensor

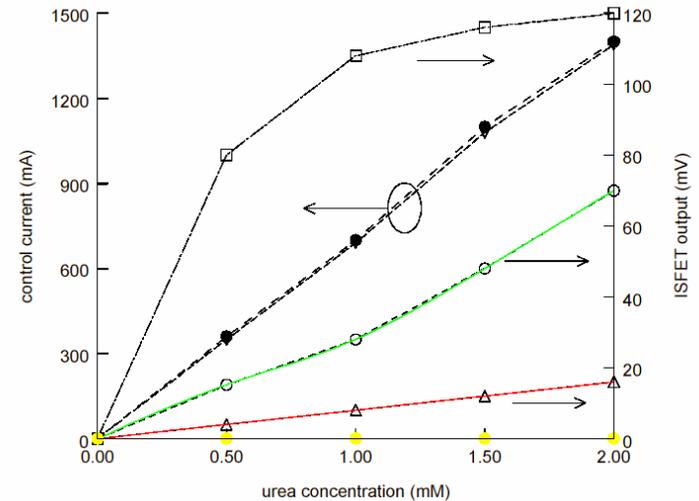


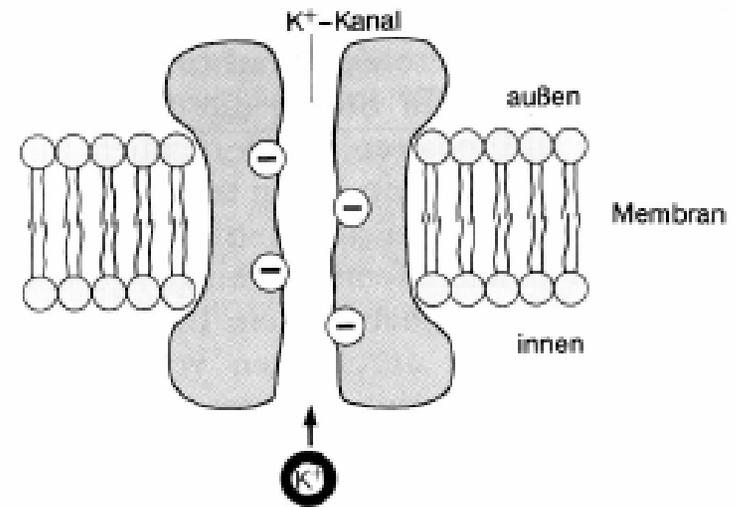
Fig. 13
Response of a classical ISFET-based enzyme sensor (open symbols) compared with that of the pH-static sensor (filled symbols) in sample solutions with different buffer capacity.

◻ : low buffer; ● : medium buffer; ▲ : high buffer

BIOFET

- **Basic Principle**

- Interaction of biological system with a FET structure
- Electrochemical processes in cells
 - **Cell membrane: embedded ion channels allow ion transfer**
 - **Potential drop:**
 - **action potential: induced change of permeability**



Depolarisation

Opening of quick channels
→ Potentialstep in U_{Membrane}

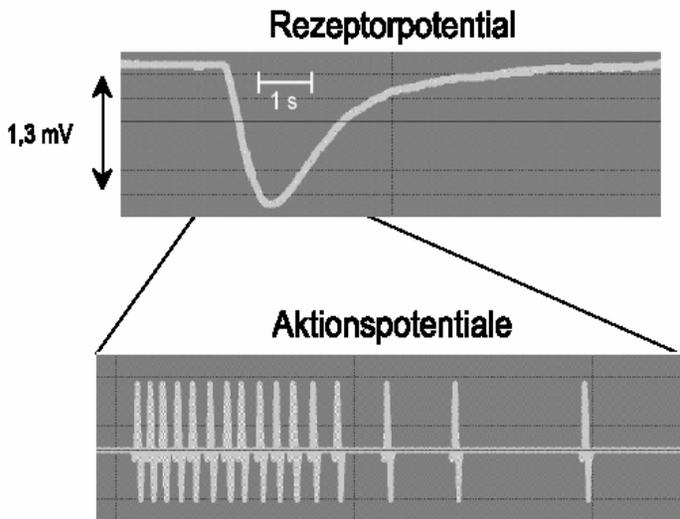
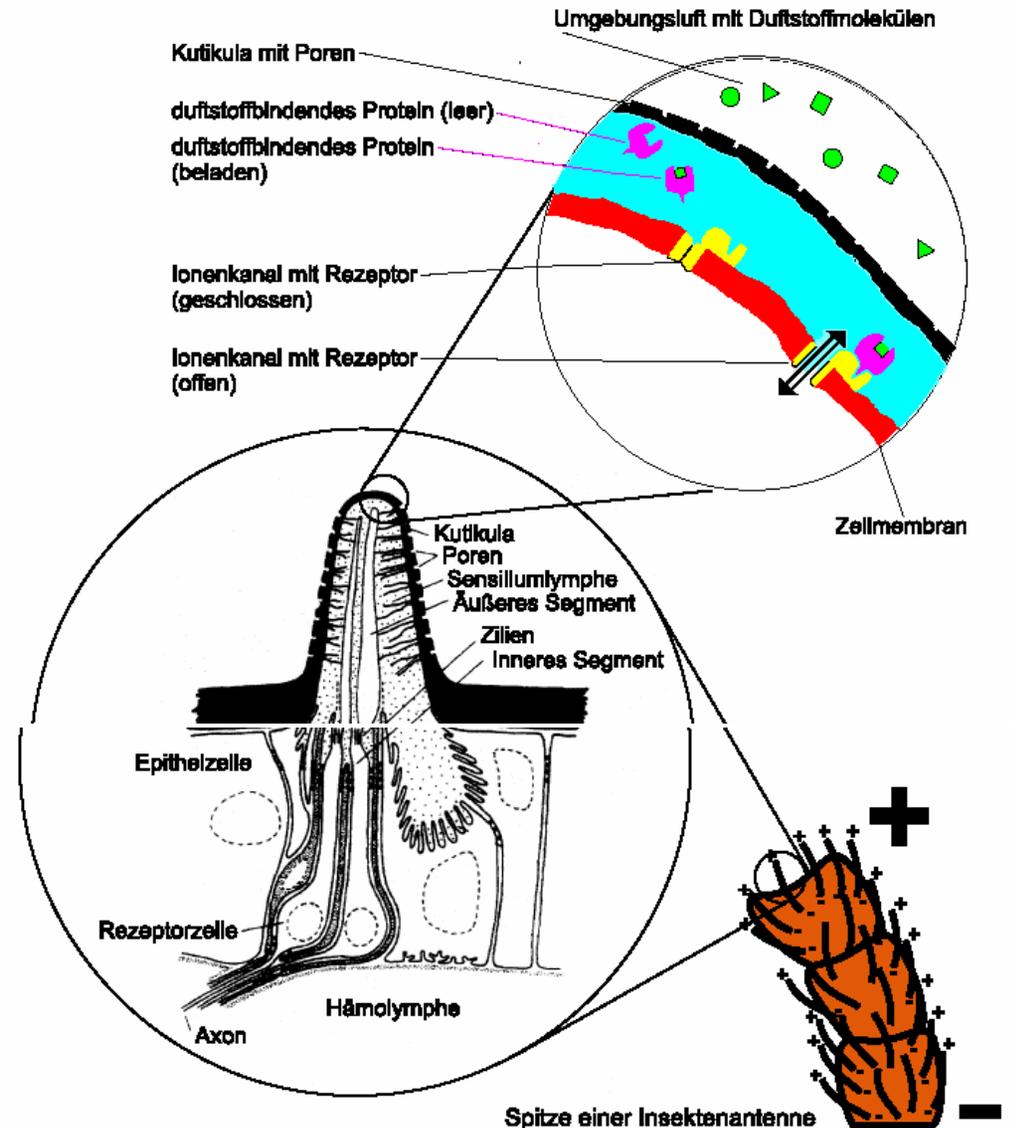
Repolarisation

Opening of slow channels →
 $U_{\text{Membrane}} = \text{ignition value}$

BIOFET

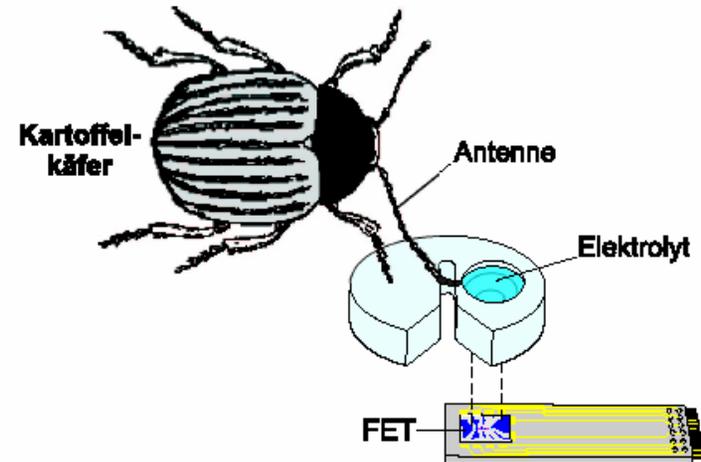
- Insect antenna

- Information of $[S]$ is transformed in an electrical signal
- Polarisation in sensing hairs
- Total dipole along the antenna
- Receptorpotential \rightarrow action potential

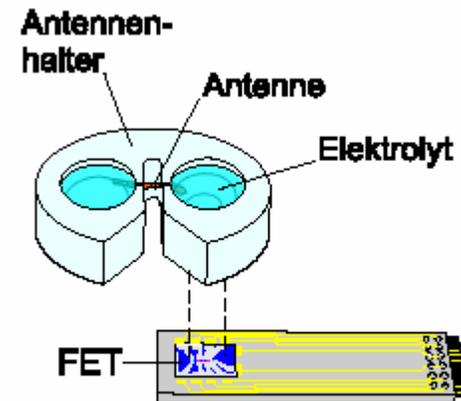


BIOFET

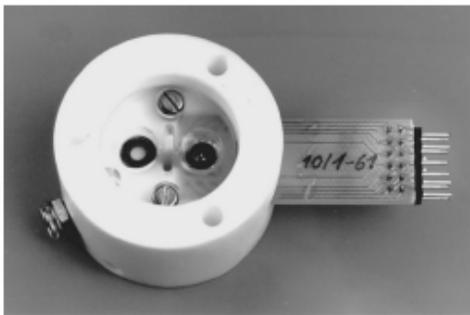
- Coupling of antenna and FET
 - electrolyte
 - constant-Voltage mode: change of antenna potential causes change in FET surface potential
 - local peak in I_D ([S])



A) Whole-Beetle-Anordnung



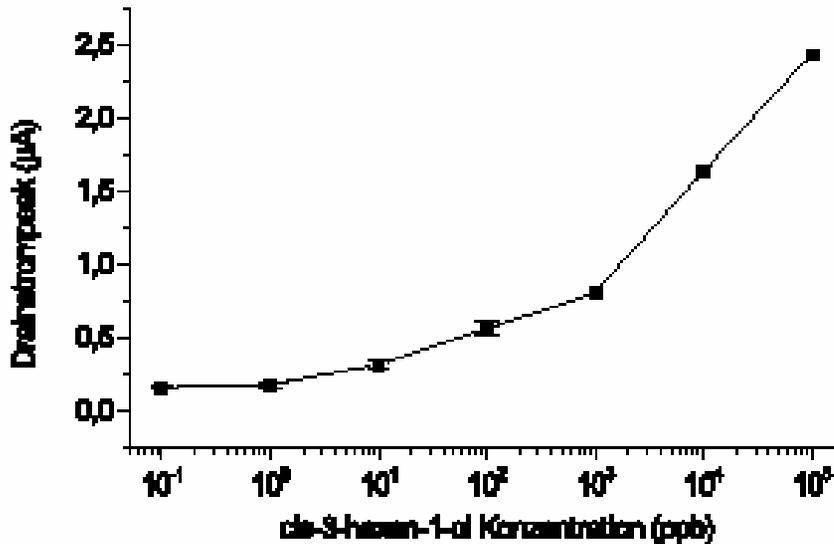
B) Isolated-Antenna-Anordnung



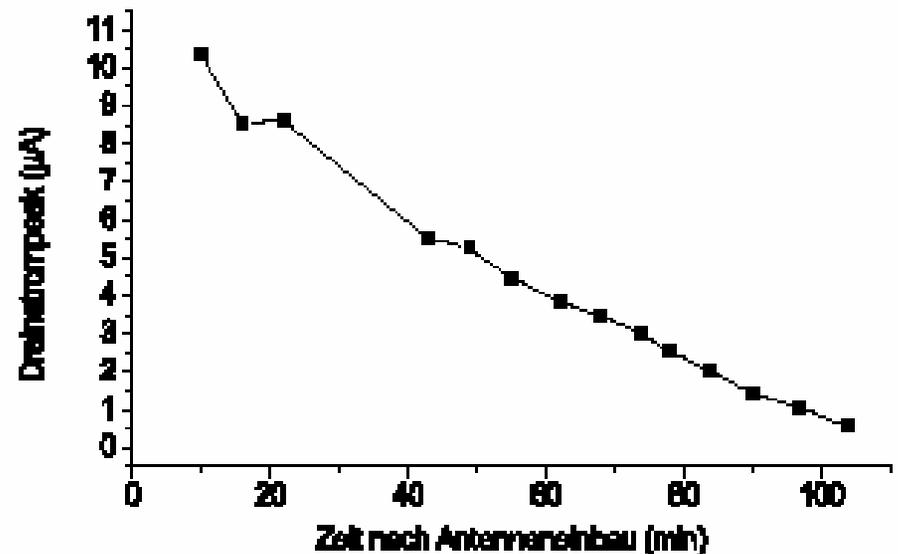
C) Sensorkopf mit Antennenhalter und FET

BIOFET

- Correlation between peak amplitude and [S] → sensing of [S]

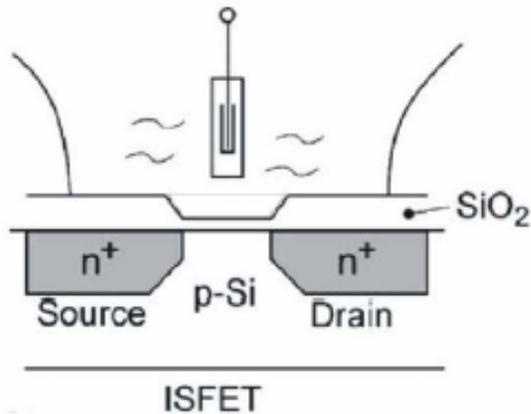


- Possible application
 - Agriculture (*Leptinotarsa decemlineata*)
 - Fire detection (*Phaenops cyanea*)



Surface Charge sensitivity

DNA sensor



- Gate potential controlled by the electrical charge associated with the gate interface.
- surface charge sensitivity ?

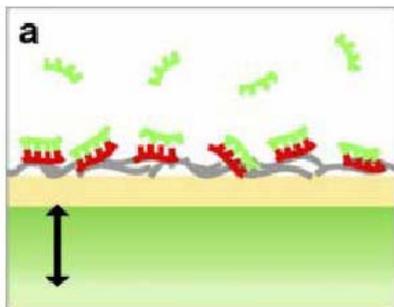
Surface charge density and surface potential

$$\sigma_0 = \sqrt{8kT\epsilon\epsilon_0 n^0} \sinh\left(\frac{q\psi_0}{2kT}\right)$$

Grahame equation

DNA: intrinsic negative charge at sugarphosphate backbone

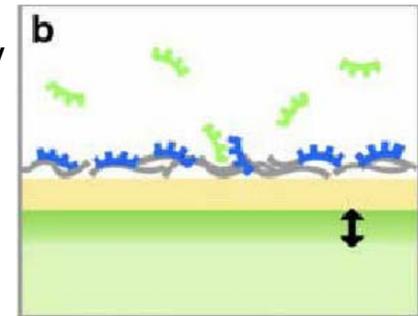
Probe DNA: bound to PLL surface



Target DNA: binding to complementary DNA
 → surface charge
 → depletion
 → region, potential change

Probe DNA: bound to PLL surface

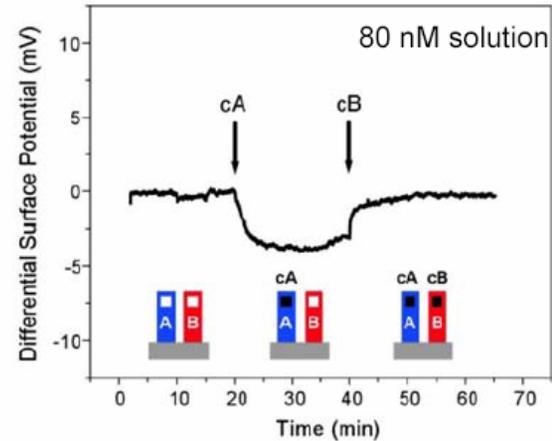
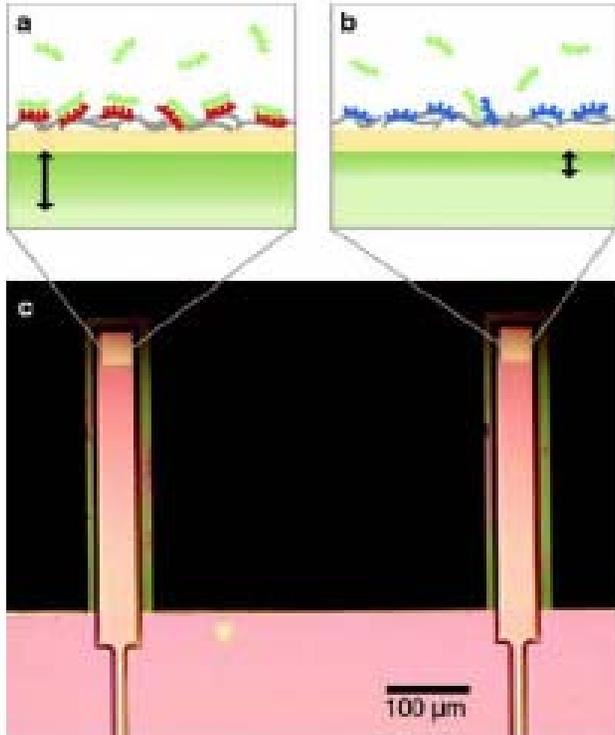
noncomplementary DNA:
 → No binding



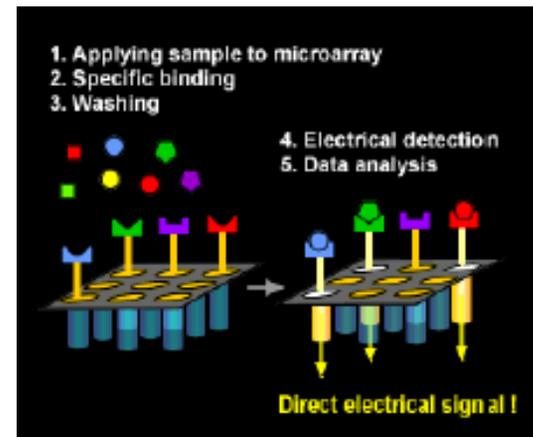
Surface Charge sensitivity

DNA sensor

Measurement of the differential surface potential enables DNA detection



- resolution: 2nM or 8ng/ml DNA
- 3×10^4 hybridized 12-mer oligonucleotides/ μm^2 $\rightarrow \approx 3\text{mV}$



Application of New Materials

GaN

Advantages of wide-bandgap materials:

- i) no generation of unwanted charge carriers (optical, thermal)
- ii) Strong chemical bondings → mechanical and thermal stability

Sensor concept: modulation of charge carrier density in 2DEG near the AlGaN/GaN interface

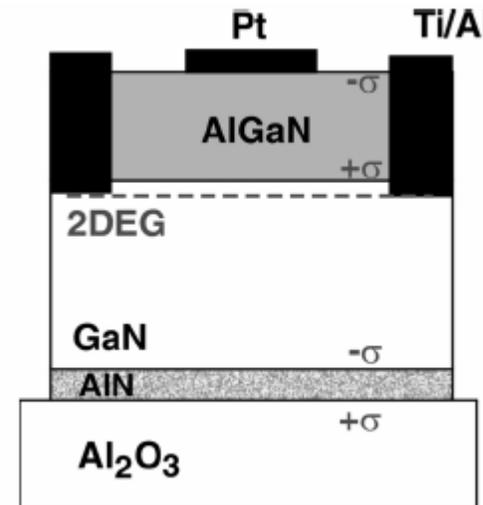
Formation of a 2DEG:

Dicontinuity of microscopic dipole density in the wurzite crystal at the AlGaN / GaN interface

Strong electronegativity of N

→ dipole moments along the bondings between Ga – N / Al - N

AlGaN / GaN heterostructure



Application of New Materials

GaN

Different strength of ionic bonds of III-nitrides



Change of macroscopic polarisation P at the AlGaN / GaN interface

$$P_{\text{AlGaN}} > P_{\text{GaN}}$$



Electrostatics

Surface charge with opposite sign at the two surfaces perpendicular to P

$$\sigma = P$$



$$E = \sigma / \epsilon_0 (\epsilon - 1) =$$

Internal electric field permanent polarisation

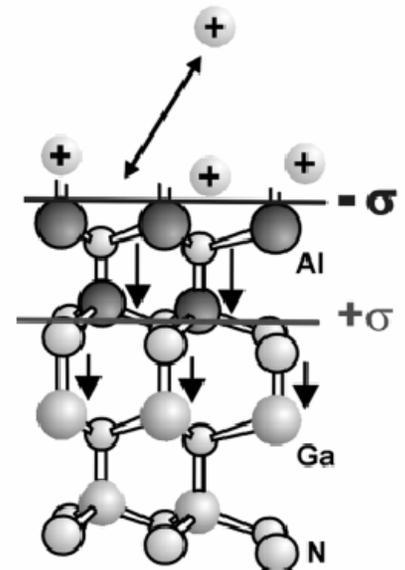
Internal interface: consider $\Delta P = P_{\text{AlGaN}} - P_{\text{GaN}}$



Surface charge $+\sigma$ at AlGaN / GaN

Surface charge $-\sigma$ at terminated at AlGaN surface

Interacts with surrounding compensating ions



Application of New Materials

GaN

Surface charge between GaN / substrate interface can be neglected

Potential landscape:

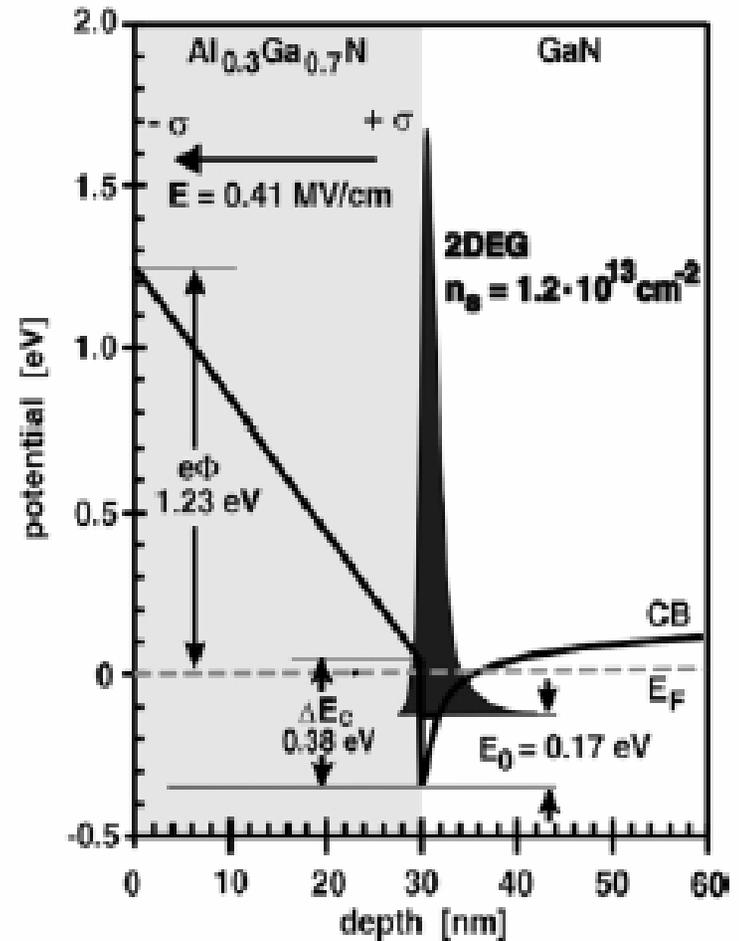
$+\sigma \Rightarrow$ downward bending
accumulation of electrons

High density $n_e \sim 10^{13} \text{ cm}^{-2}$

2DEG: separated from surface through insulating AlGaN layer
 \rightarrow strong confinement

Ion sensitive:

X^+/X^- adsorbed \rightarrow e^- gained / lost in 2DEG
affects conductivity / current



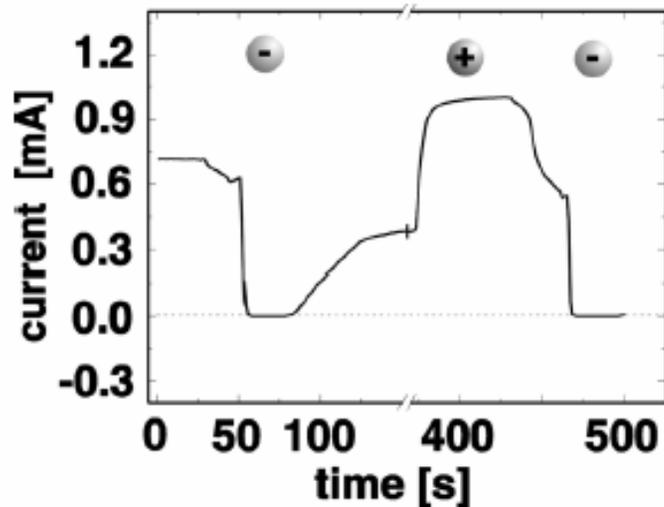
Application of New Materials

GaN

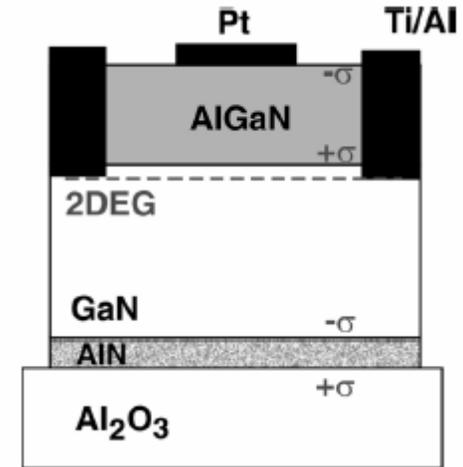
Removal of Pt-electrode → ISFET

High sensitivity:

negative ions: strong depletion
of n-channel → no current



positive ions: strong accumulation
along n -channel → current



| Ion | $\Delta\phi_{\text{surface}}/\text{dec.}$ |
|-----------|---|
| H^+ | 56 – 57mV |
| K^+ | < 2mV |
| Na^+ | < 5mV |
| Ca^{2+} | < 2mV |
| Cl^- | < 2mV |

Response: pH sensitivity near to the
Nernstian limit

Application of New Materials

GaN

Further advantages:

- high signal to noise ratio
- chemically stable
- no toxic to living cells



great potential for physiological measurements (e.g. cell potentials)

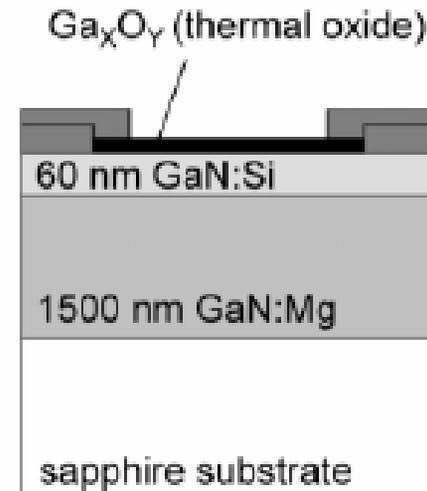
Improved heterostructure

n – doped channel: GaN:Si

p – doped bulk: GaN:Mg

→ Strong confinement of 2DEG

→ Enhanced sensitivity

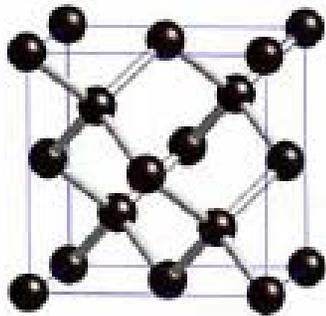


Application of New Materials

Diamond

PROPERTIES

- large bandgap (5.45 eV)
- H-termination
- O-termination
- good biocompatibility

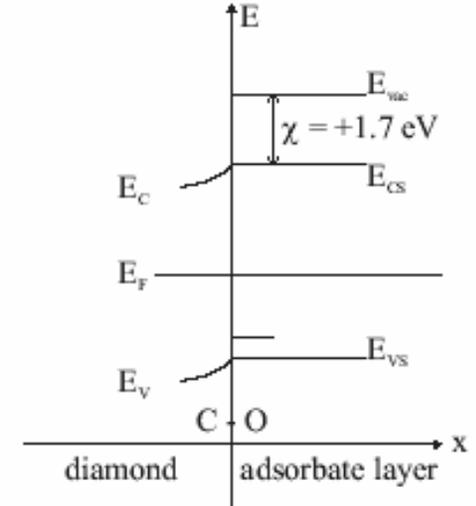
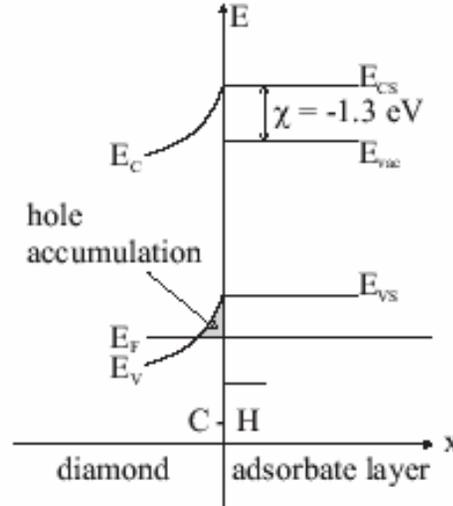


formation of dipoles



Influence on electron affinity

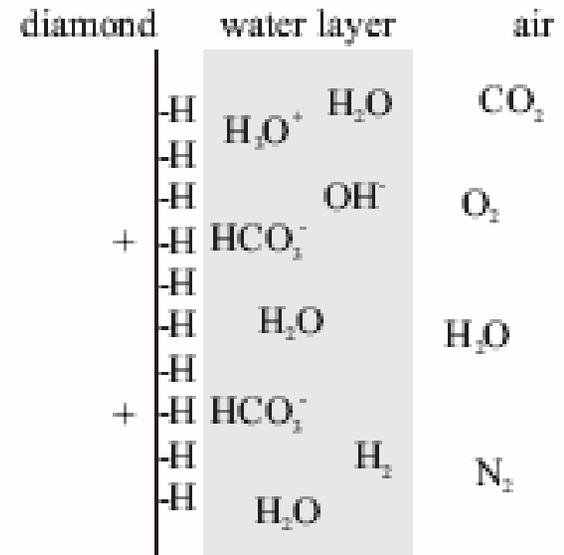
$$= \chi = E_{vac} - E_{cs}$$



Application of New Materials

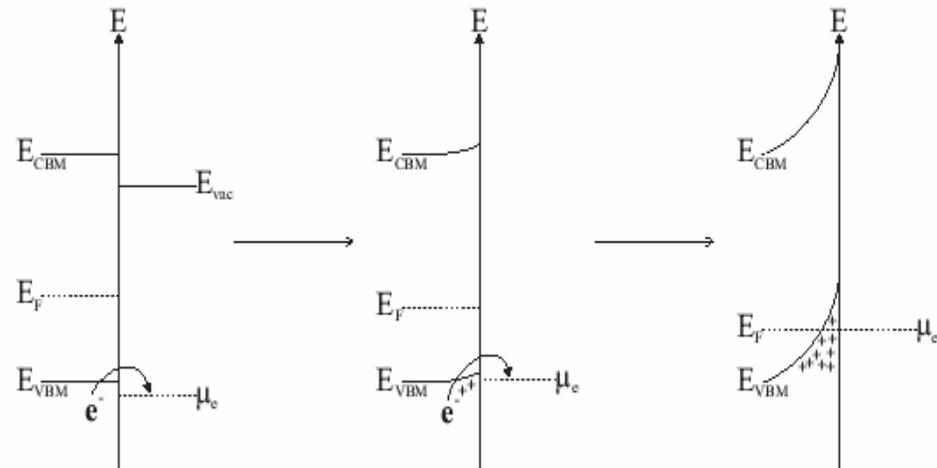
Diamond

- Surface conductivity of H-terminated diamond (Transfer-Doping-Model)
 - air exposure is essential
 - spontaneously formation of acidic water layer
 - redox reaction



electron transfer
into the liquid ($\mu_e < E_F$)

$$\rho_s = 10^{13} \text{ cm}^{-2}$$

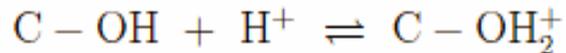


Application of New Materials

Diamond

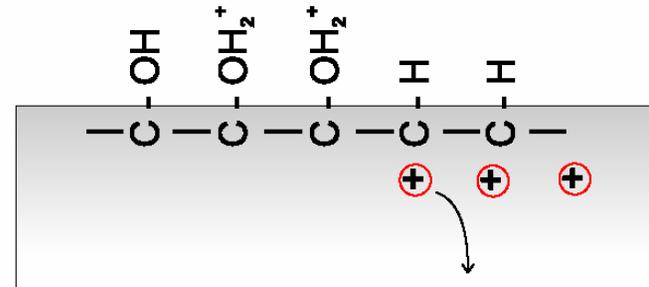
- pH-sensitivity of O-terminated diamond

- Ozon treatment of H-terminated surfaces
- amphoteric behaviour

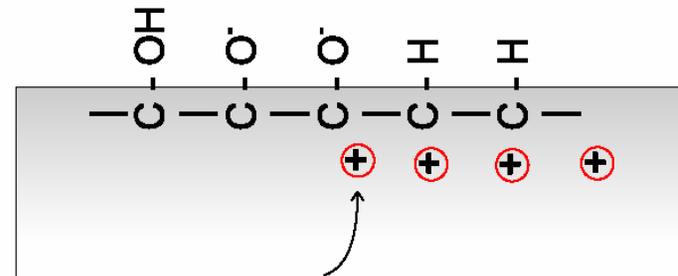


- pH-sensitivity:
site binding model

modulation of 2-D hole gas at H-terminated sites



(a) low pH - reducing accumulation of holes in the channel

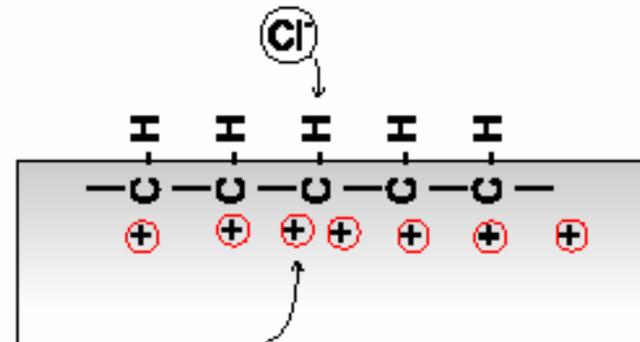


(b) high pH - enhancement of hole density in the channel

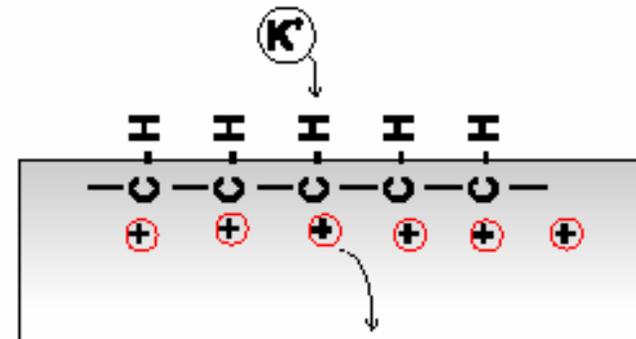
Application of New Materials

Diamond

- Ion Sensitivity (Kawarada, 2002)
 - H – terminated diamond shows sensitivity to anions and cations (e.g. Cl^- , I^- , Br^-)



(a) anions

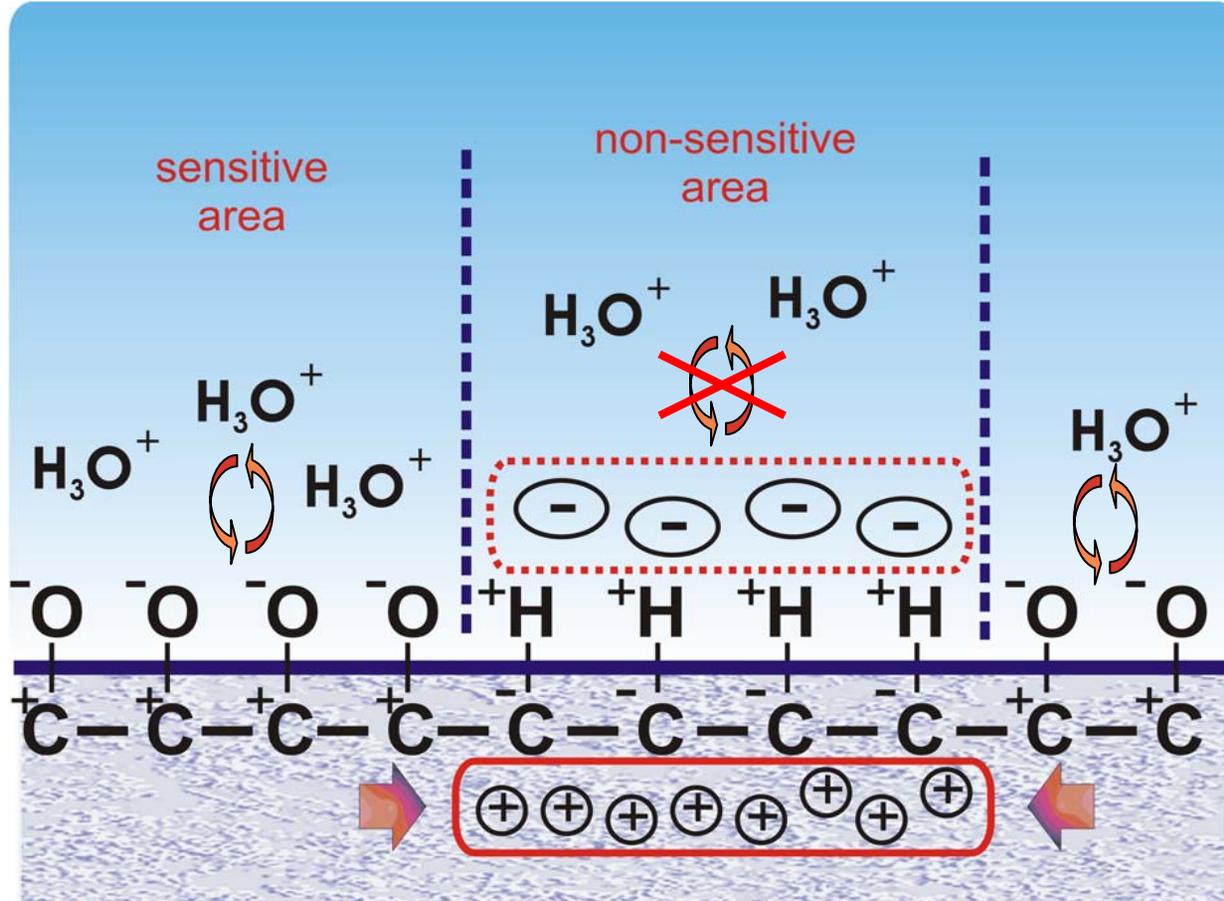


(b) cations

Not reproducible so far

Application of New Materials

Diamond

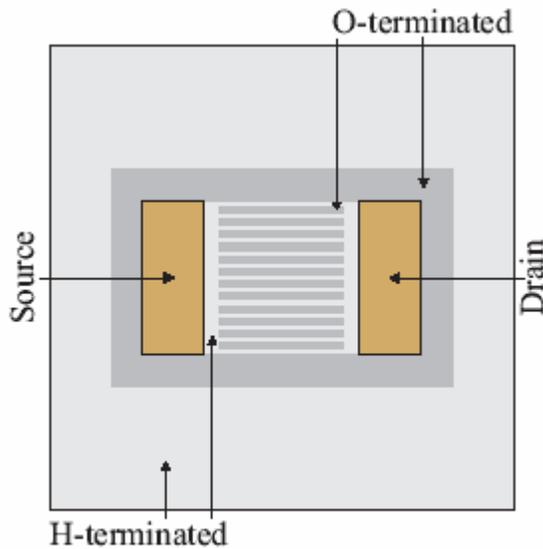


lateral modulation of the conductive channel

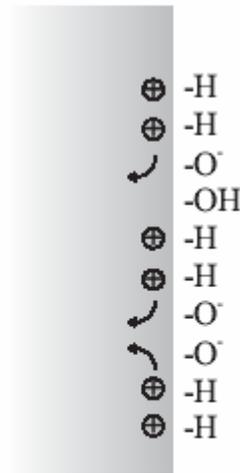
Application of New Materials

Diamond

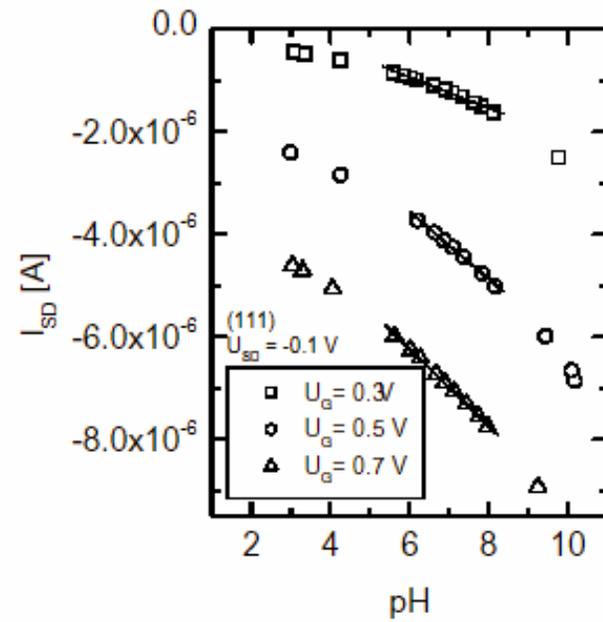
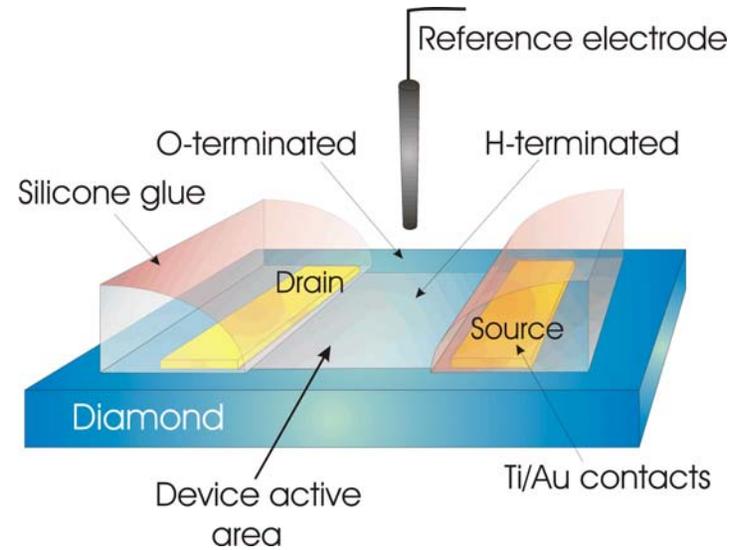
- pH-sensitive Device
 - Combination of „conducting“ H-terminated and „pH-sensitive“ O-terminated areas



(a) sample top view



(b) crosssection



Conclusions

- ISFET: basis for many bio-/chemical sensors
- Miniaturizing and high integration
- No commercial breakthrough, caused by:
 - High drift
 - Miniaturization of reference electrodes (insufficient stability)
 - Exposure to corrosive electrolytes (lifetime): improved passivating necessary

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- **[6]** K.-S. Song, T. Sakai, H. Kanazawa, Y. Araki, H. Umezawa, M. Tachiki and H. Kawarada: *Cl⁻ sensitive biosensor used electrolyte-solution-gate diamond FETs*, Biosensors and Bioelectronics 19, 137 (2003)
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- **[9]** S. Sze, *Physics of Semiconductor Devices*, second edition, John Wiley & Sons, 362 – 391, 430 – 445 (1985)

THANK YOU FOR YOUR
ATTENTION!

Questions?